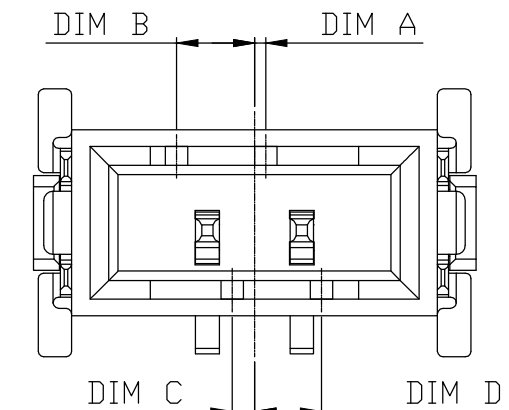
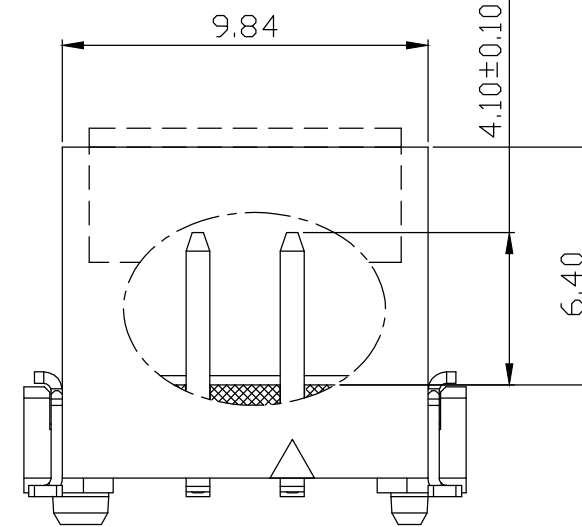
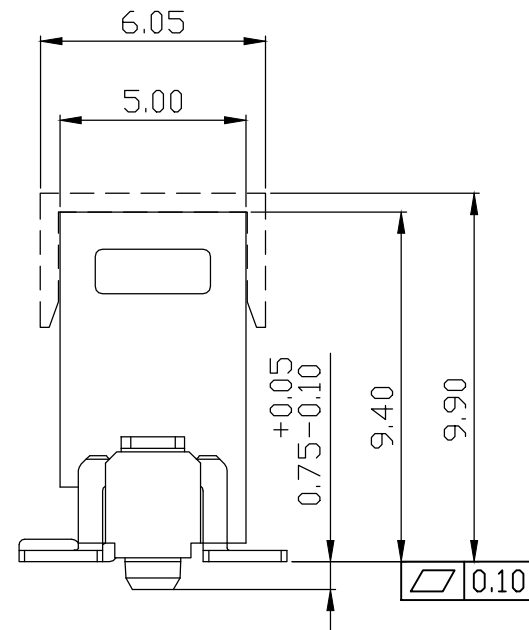
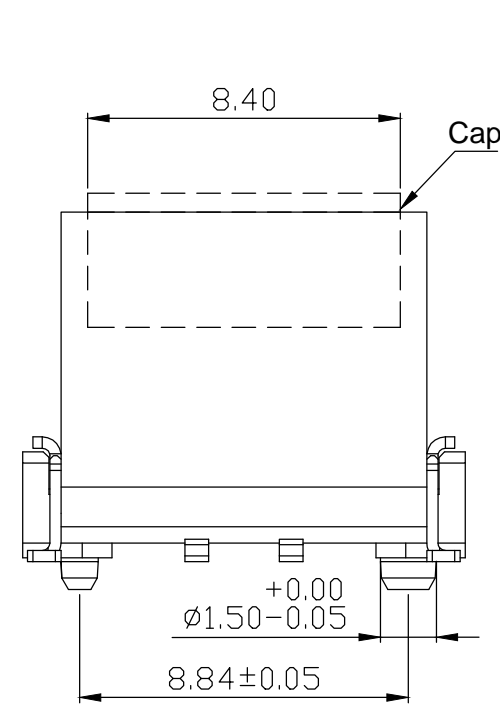


RECOMMENDED PCB LAYOUT(TOP VIEW)
PCB BOARD TOLERANCE:±0.05

NOTE:

- 1.MATERIAL:
 - 1.1 Insulator:LCP,UL94V-0,Black
 - 1.2 Contact:Copper Alloy
2. FINISH
 - 2.1 Contact:Au 15u" over nickel on contact area,Matte Tin over Nickel on solder area
- 3.ELECTRICAL
 - 3.1 Current Rating:12A Max.
 - 3.2 Contact Resistance:20mΩ Max.
 - 3.3 Withstand Voltage:2000V AC
 - 3.4 Insulation Resistance:1000 MΩ min
- 4.Operating temperature:-55°C TO +150°C
- 5.Soldering temperature:260°C for 3~5S
- 6.Packing: Tape Reel+Cap



COLOR	DIMENSION			
	DIM A	DIM B	DIM C	DIM D
BLACK	0.30	2.10	0.6	1.8

RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2025	Peter
Modification	Date	Name



Date	Name	Description: Wire to Board Wafer Pitch 2.54mm 2Pin Straight SMT
03.03.2025	Peter	
Approved	03.03.2025	ASSMANN WSW-NO.
		A-WBP-M005EG-02SR1
Drawing-No.		rev00
ASS 10022 CO		
Customer-No.		Sheet 1 / 26

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A

B

C

D

E

F

A

B

C

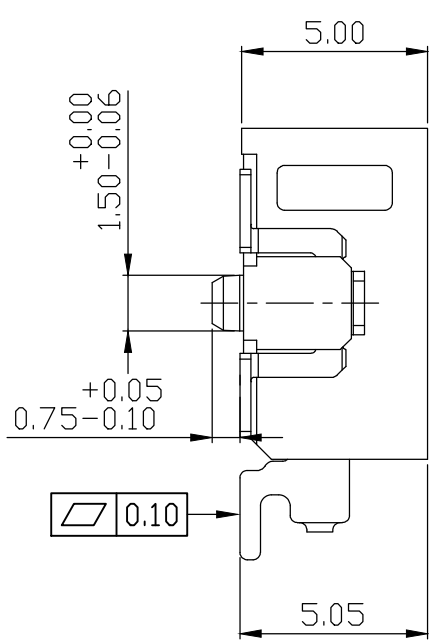
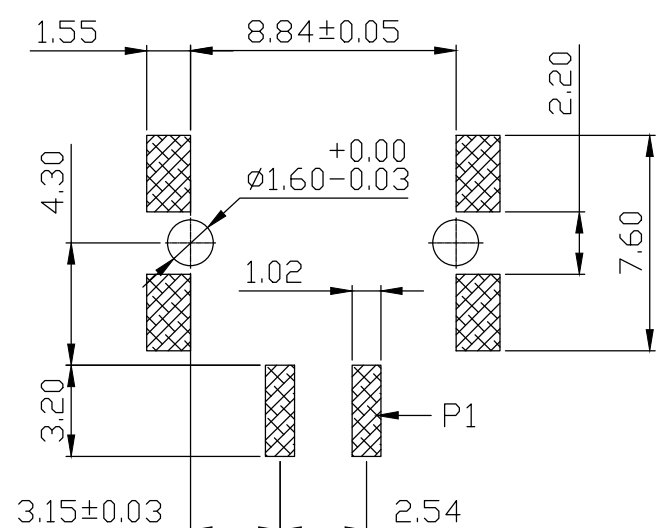
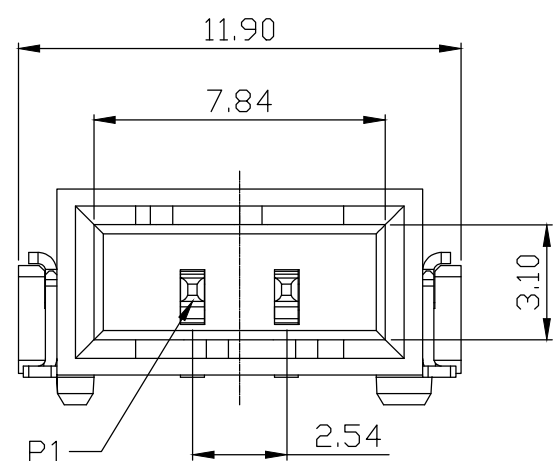
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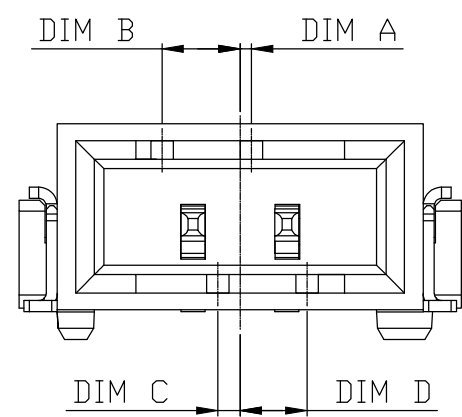
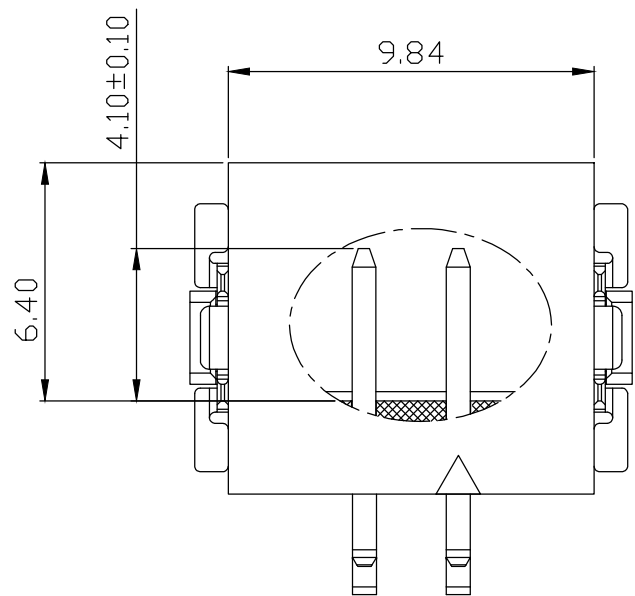
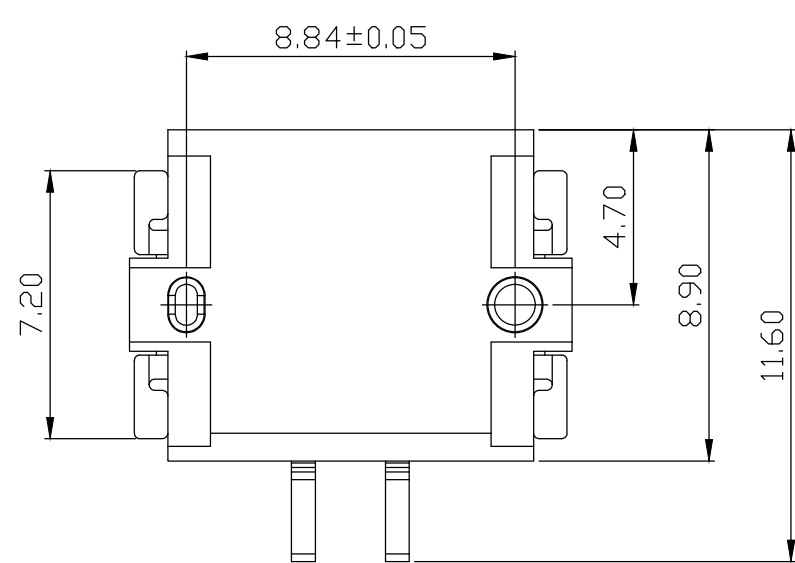
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NOTE:

- 1.MATERIAL:
 - 1.1 Insulator:LCP,UL94V-0,Black
 - 1.2 Contact:Copper Alloy
- 2. FINISH
 - 2.1 Contact:Au 15u" over nickel on contact area, Matte Tin over Nickel on solder area
- 3.ELECTRICAL
 - 3.1 Current Rating:12A Max.
 - 3.2 Contact Resistance:20mΩ Max.
 - 3.3 Withstand Voltage:2000V AC
 - 3.4 Insulation Resistance:1000 MΩ min
- 4.Operating temperature:-55°C TO +150°C
- 5.Soldering temperature:260±5 °C for 3-5S
- 6.Packing: Tape Reel

RECOMMENDED PCB LAYOUT(TOP VIEW)
PCB BOARD TOLERANCE:±0.05



COLOR	DIMENSION			
	DIM A	DIM B	DIM C	DIM D
BLACK	0.30	2.10	0.6	1.8

RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2024	Peter
Modification	Date	Name

Date: 03.03.2025
Name: Peter
Drawn: 03.03.2025
Approved: 03.03.2025
Peter

ASSMANN
WSW components
A company of BCS

Description: Wire to Board Wafer 2Pin Pitch 2.54mm Right Angle SMT	
ASSMANN WSW-NO. A-WBP-M005EA-02SR1	
Drawing-No. ASS 10022 CO	rev00
Customer-No.	Sheet 2 / 26

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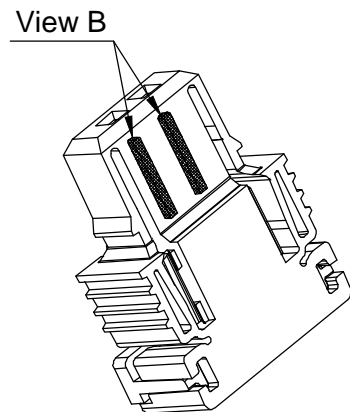
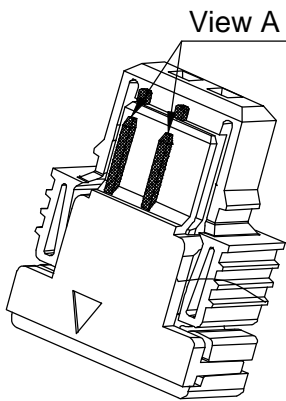
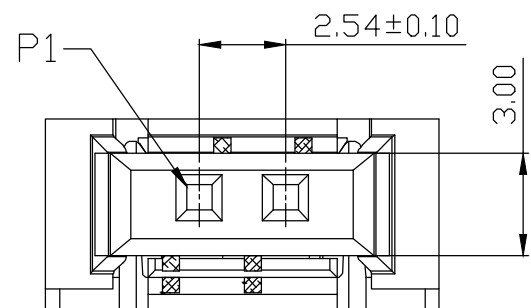
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A

A



NOTE:

1.MATERIAL:

1.1 Housing:PA46,UL94V-0,Black

2.ELECTRICAL

2.1 Withstand Voltage:2000V AC

2.2 Insulation Resistance:1000 MΩ min

3.Operating temperature:-55°C TO +125°C

4.Packing:Tray

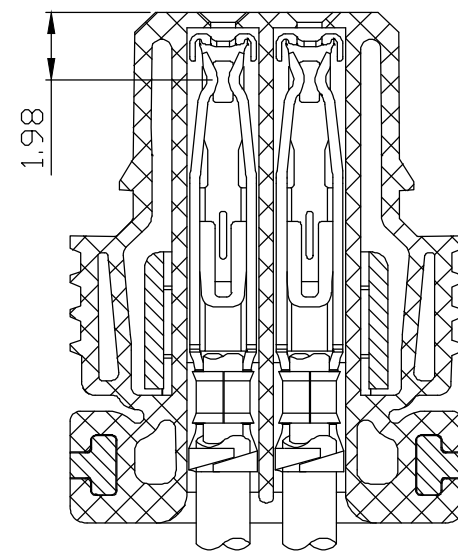
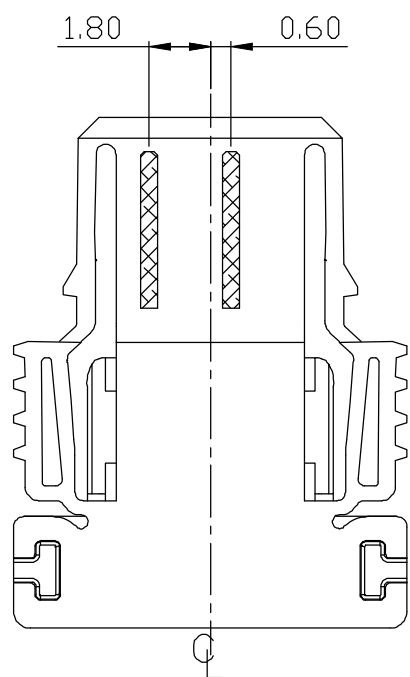
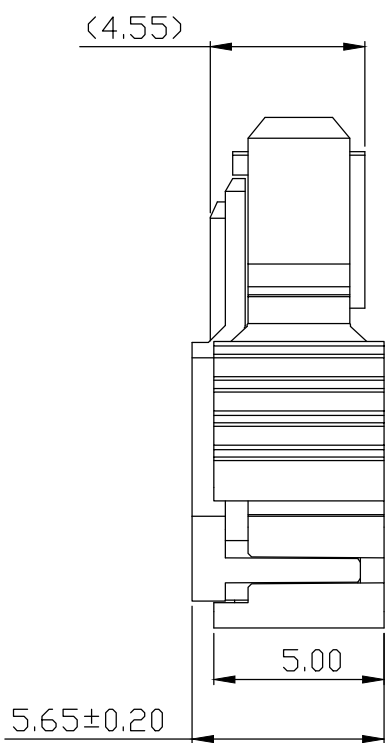
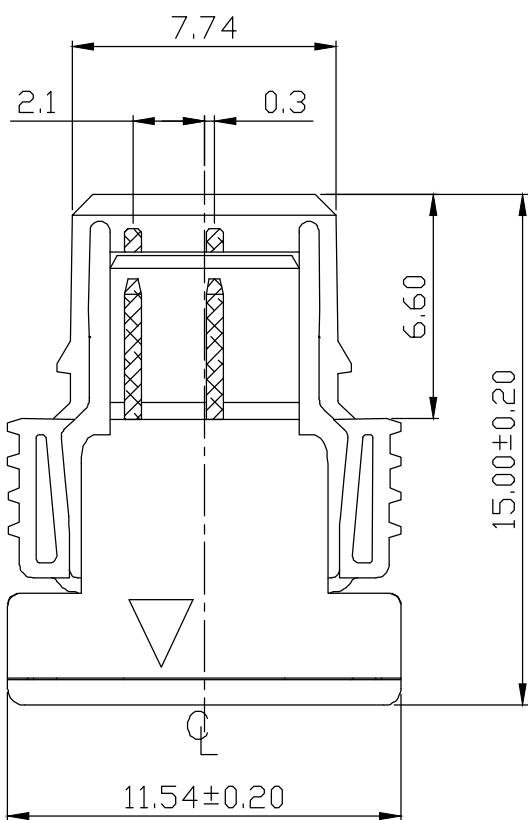
B

B

C

C

Fool Proof Diagram



Terminal Diagram

D

D

E

E

F

F

G

G

RoHS compliant

unit:mm

Scale Free

TOLERANCE

.X ±0.40

.XX ±0.25

.XXX ±0.15

DIM TOL

X.° ±3°

Angle TOL

①

Drawn

03.03.2025

Id.

Modification

Date

Name

Date

Name

Description: Wire to Board Housing
Pitch 2.54mm 2Pin

Drawn

03.03.2025

Peter

Approved

03.03.2025

Peter

ASSMANN WSW-NO.

A-WBH-M005EG-02CP1

Drawing-No.

ASS 10022 CO

rev00

Customer-No.

Sheet
3 / 26

H

H

1

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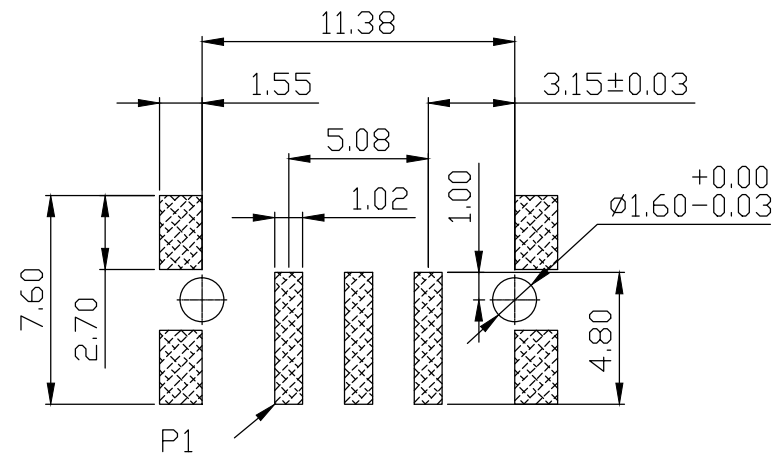
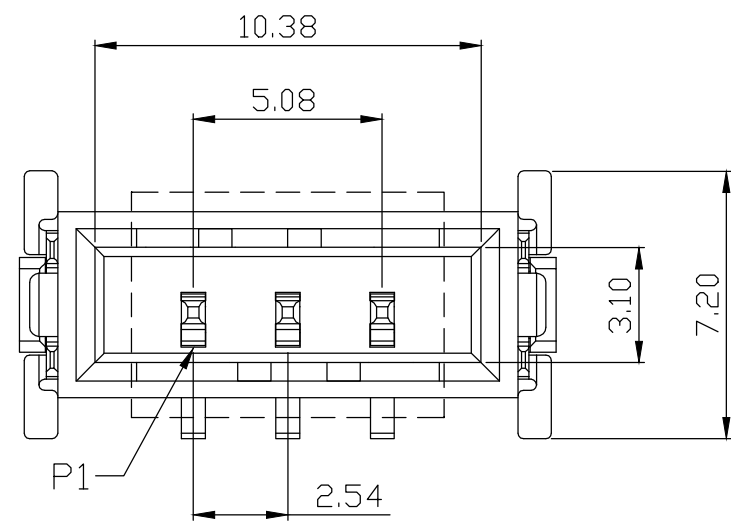
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RECOMMENDED PCB LAYOUT(TOP VIEW)
PCB BOARD TOLERANCE:±0.05

NOTE:

1.MATERIAL:

- 1.1 Insulator:LCP,UL94V-0,Black
- 1.2 Contact:Copper Alloy

2. FINISH

- 2.1 Contact: Au 15u" over nickel on contact area, Matte Tin over Nickel on solder area

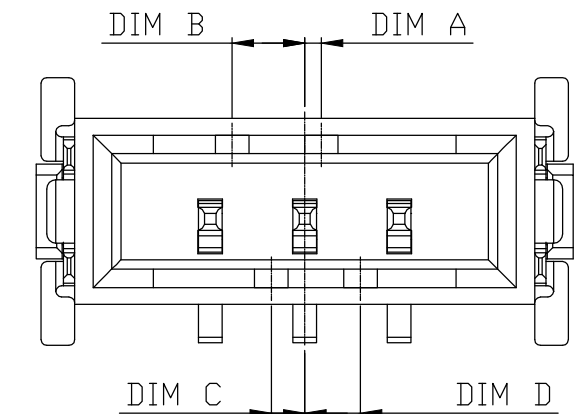
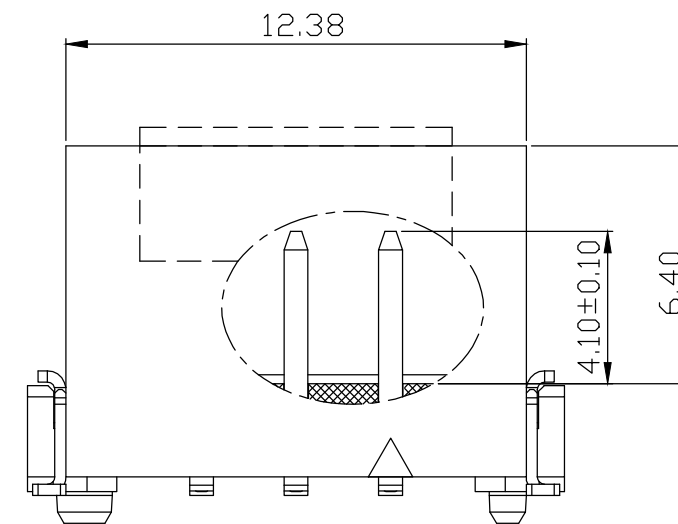
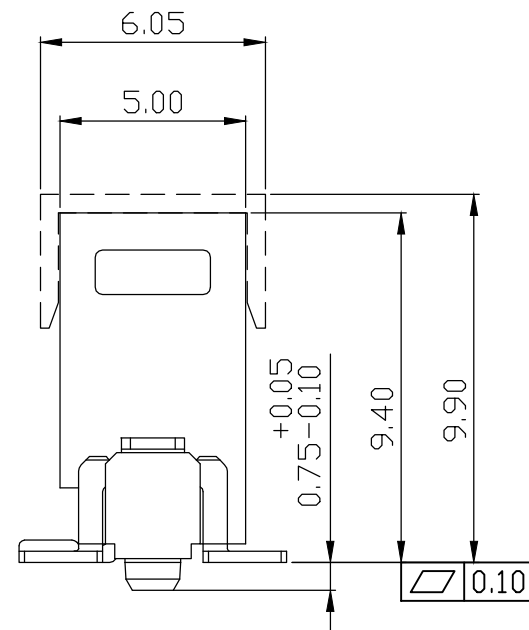
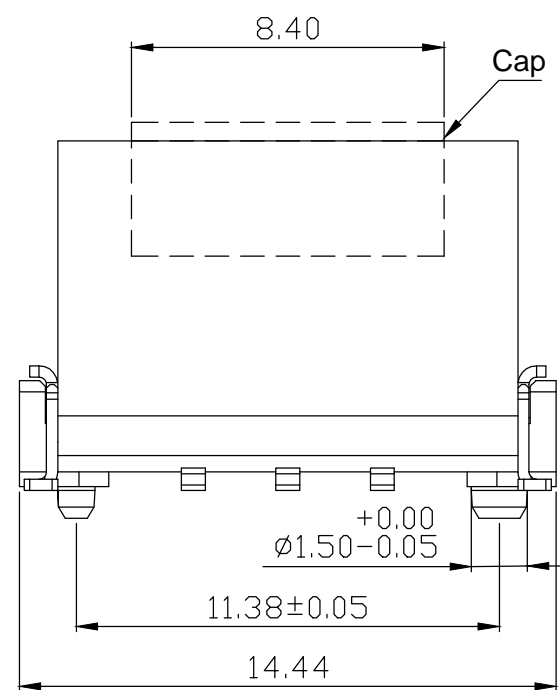
3.ELECTRICAL

- 3.1 Current Rating:12A Max.
- 3.2 Contact Resistance:20mΩ Max.
- 3.3 Withstand Voltage:2000V AC
- 3.4 Insulation Resistance:1000 MΩ min

4.Operating temperature:-55°C TO +150°C

5.Soldering temperature:260°C for 3~5S

6.Packing: Tape Reel+Cap



COLOR	DIMENSION			
	DIM A	DIM B	DIM C	DIM D
BLACK	0.45	1.95	0.9	1.5

RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2025	Peter
Approved	03.03.2025	Peter
Modification	Date	Name



Description: Wire to Board Wafer Pitch 2.54mm 3Pin Straight SMT	
ASSMANN WSW-NO. A-WBP-M005EG-03SR1	
Drawing-No. ASS 10022 CO	rev00
Customer-No.	Sheet 4 / 26

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A

B

C

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H

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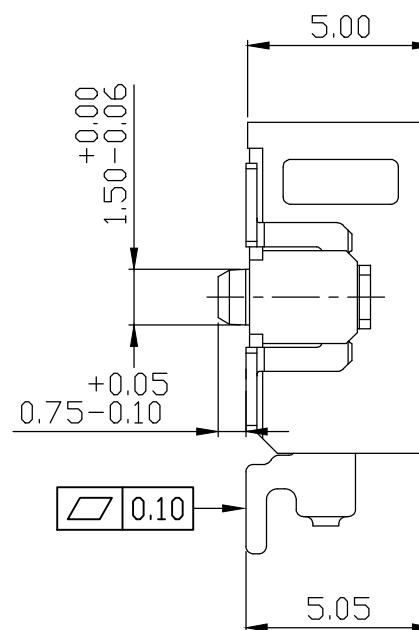
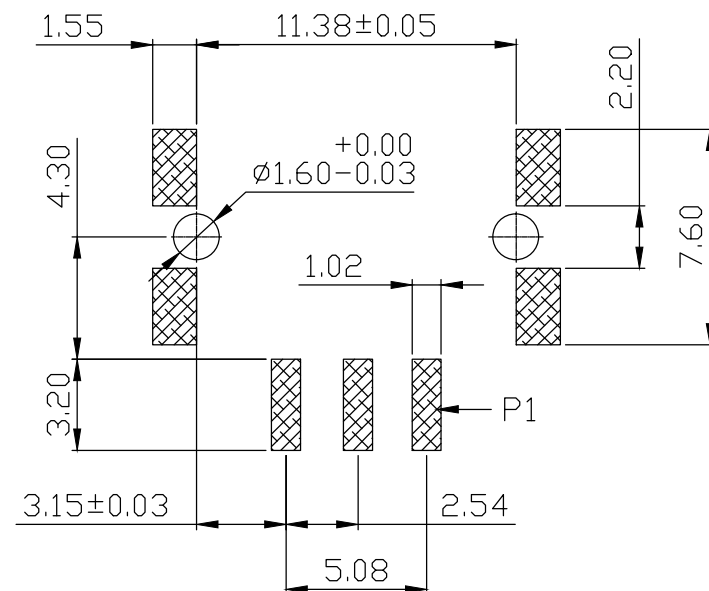
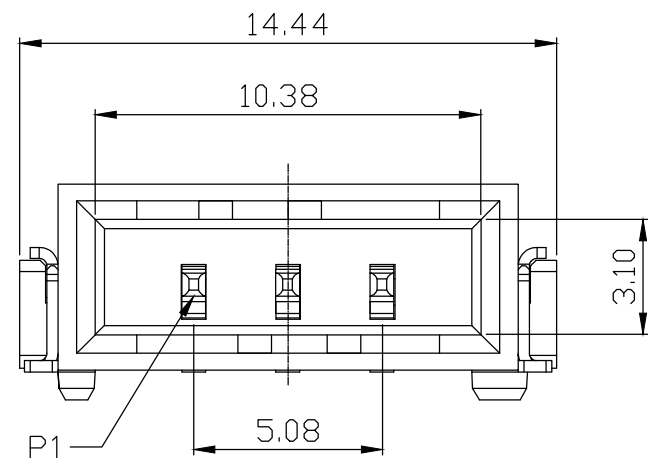
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NOTE:

1.MATERIAL:

- 1.1 Insulator:LCP,UL94V-0,Black
- 1.2 Contact:Copper Alloy

2. FINISH

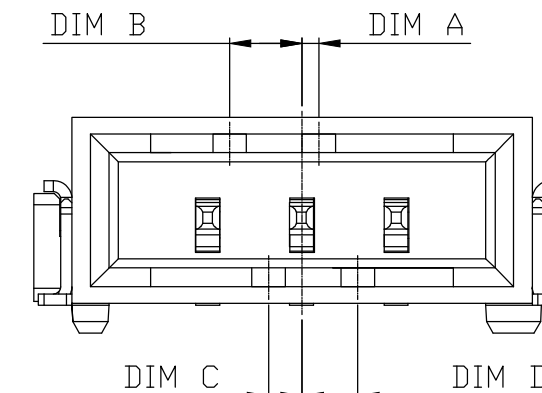
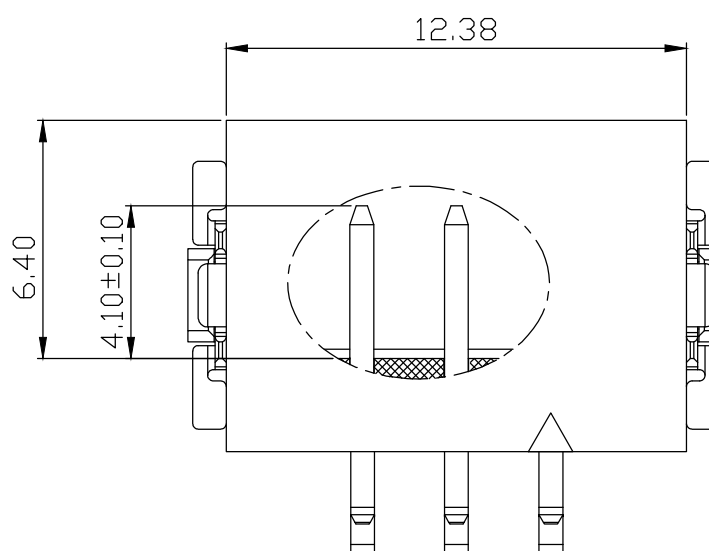
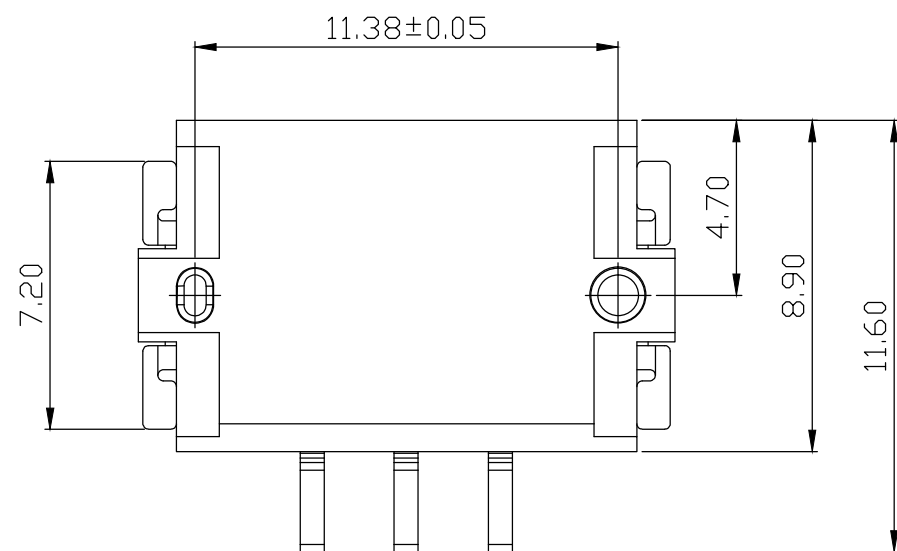
- 2.1 Contact: Au 15u" over nickel on contact area, Matte Tin over Nickel on solder area

3.ELECTRICAL

- 3.1 Current Rating:12A Max.
- 3.2 Contact Resistance:20mΩ Max.
- 3.3 Withstand Voltage:2000V AC
- 3.4 Insulation Resistance:1000 MΩ min

- 4.Operating temperature:-55°C TO +150°C
- 5.Soldering temperature:260±5°C for 3-5S
- 6.Packing: Tape Reel

RECOMMENDED PCB LAYOUT(TOP VIEW)
PCB BOARD TOLERANCE:±0.05



COLOR	DIMENSION			
	DIM A	DIM B	DIM C	DIM D
BLACK	0.45	1.95	0.9	1.5

RoHS compliant

unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2024	Peter
Modification	Date	Name

Date: 03.03.2025
Name: Peter
Drawn: 03.03.2025
Approved: 03.03.2025
Peter

ASSMANN
WSW components
A company of BCS

Description: Wire to Board Wafer 3Pin Pitch 2.54mm Right Angle SMT	
ASSMANN WSW-NO. A-WBP-M005EA-03SR1	
Drawing-No. ASS 10022 CO	rev00
Customer-No.	Sheet 5 / 26

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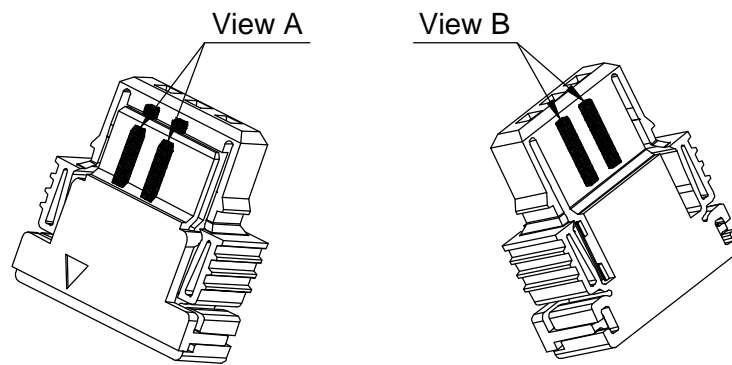
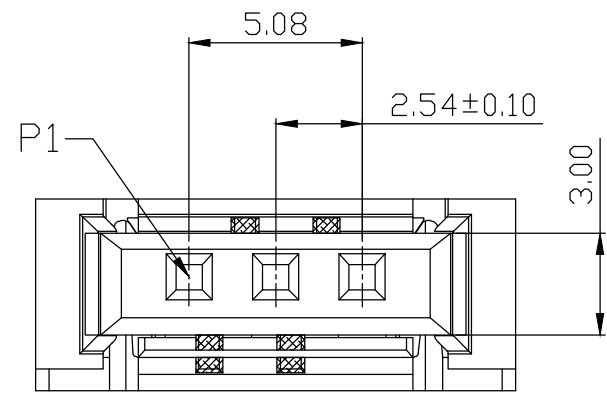
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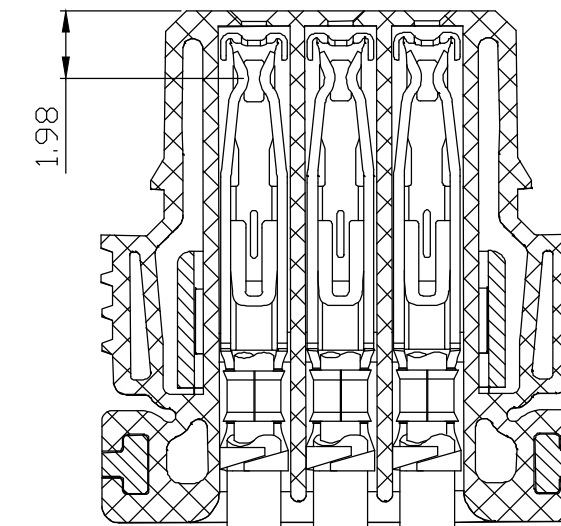
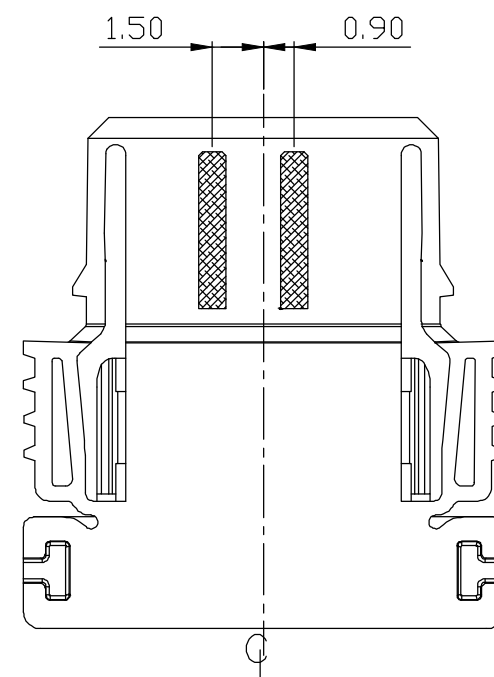
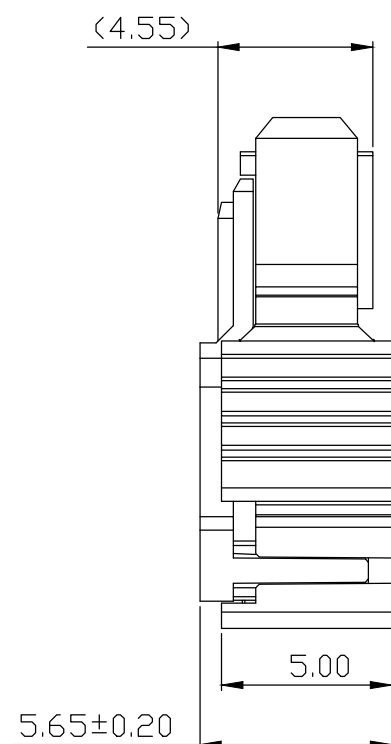
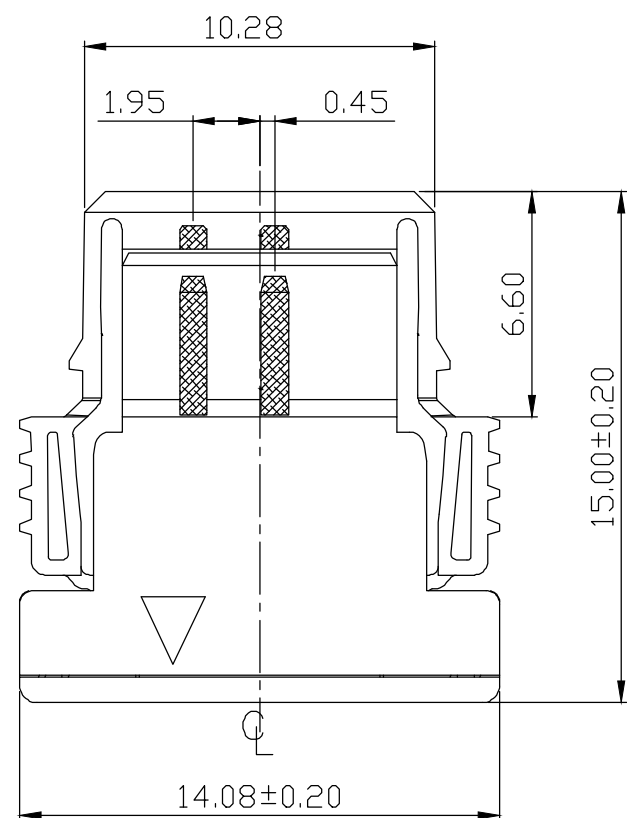
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NOTE:

- 1.MATERIAL:
 - 1.1 Housing:PA46,UL94V-0,Black
- 2.ELECTRICAL
 - 2.1 Withstand Voltage:2000V AC
 - 2.2 Insulation Resistance:1000 MΩ min
- 3.Operating temperature:-55°C TO +125°C
- 4.Packing:Tray

Fool Proof Diagram



Terminal Diagram

RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2025	Name	
Modification	Date	Name	

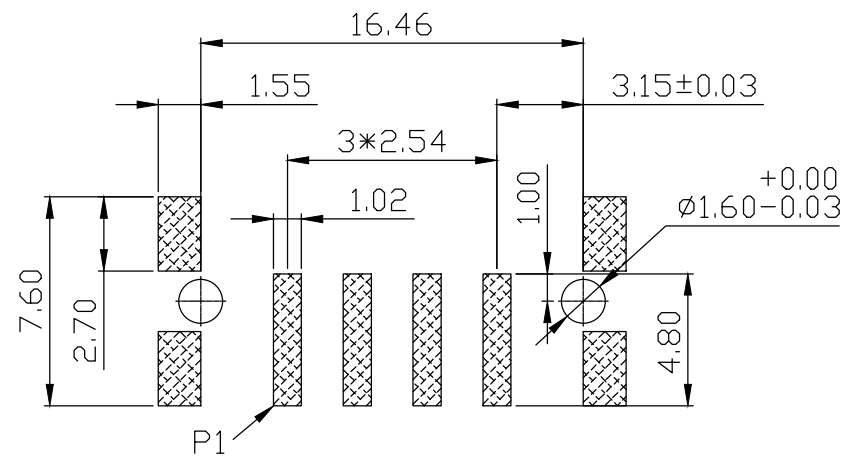
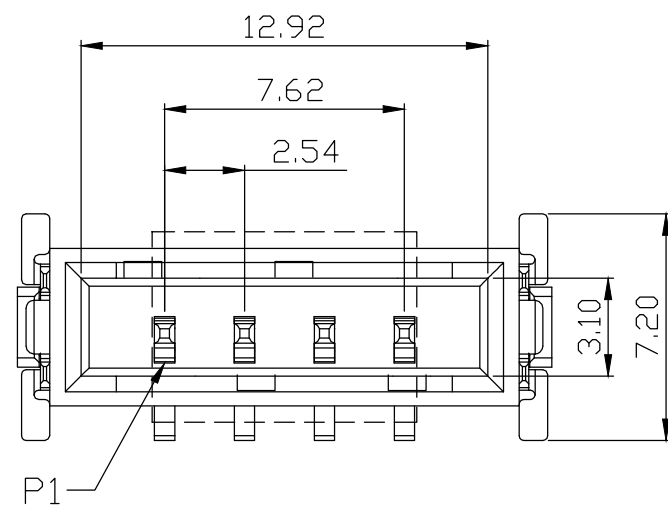


Description: Wire to Board Housing
Pitch 2.54mm 3Pin

ASSMANN WSW-NO.

A-WBH-M005EG-03CP1

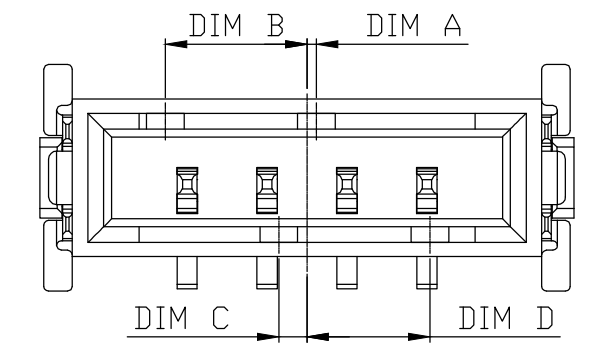
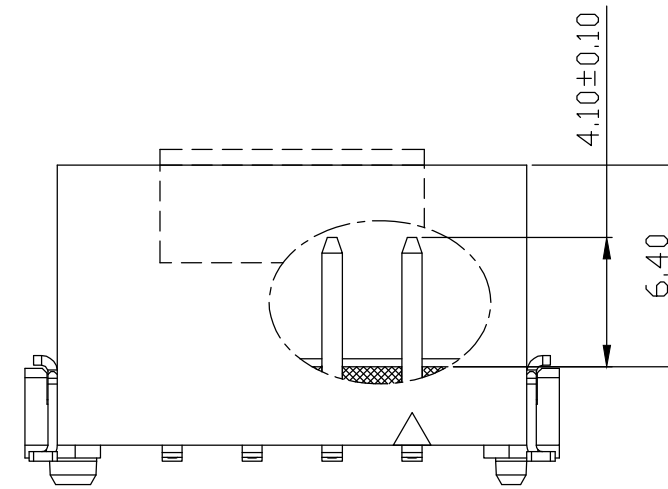
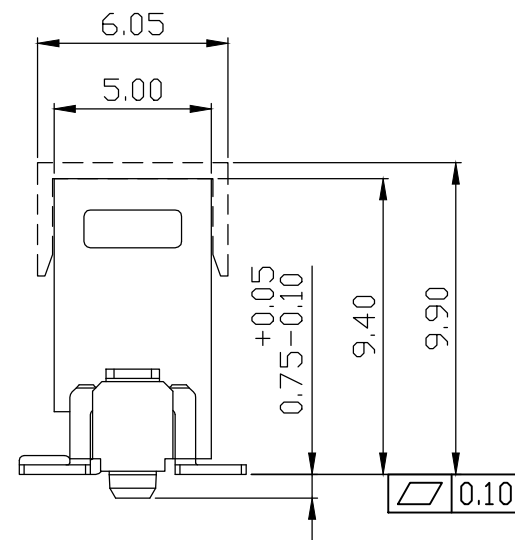
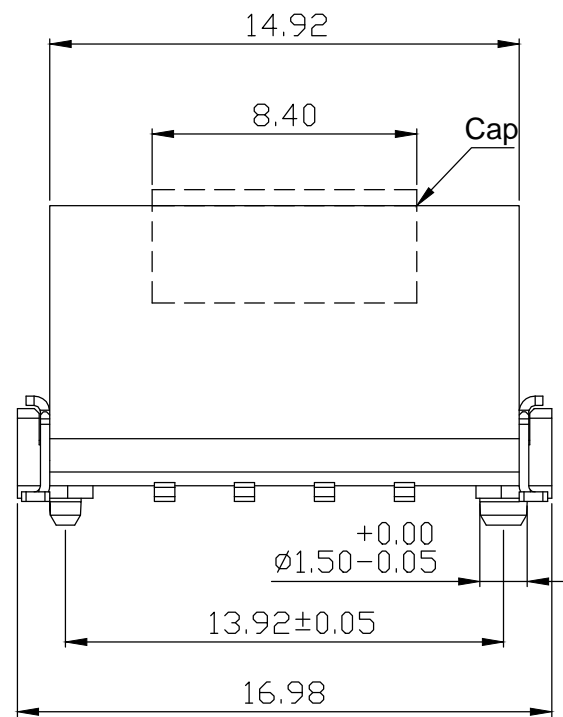
Drawing-No. **ASS 10022 CO** rev00
Customer-No. Sheet 6 / 26



RECOMMENDED PCB LAYOUT(TOP VIEW)
PCB BOARD TOLERANCE:±0.05

NOTE:

- 1.MATERIAL:
 - 1.1 Insulator:LCP,UL94V-0,Black
 - 1.2 Contact:Copper Alloy
2. FINISH
 - 2.1 Contact: Au 15u" over nickel on contact area, Matte Tin over Nickel on solder area
- 3.ELECTRICAL
 - 3.1 Current Rating:12A Max.
 - 3.2 Contact Resistance:20mΩ Max.
 - 3.3 Withstand Voltage:2000V AC
 - 3.4 Insulation Resistance:1000 MΩ min
- 4.Operating temperature:-55°C TO +150°C
- 5.Soldering temperature:260°C for 3~5S
- 6.Packing: Tape Reel+Cap



COLOR	DIMENSION			
	DIM A	DIM B	DIM C	DIM D
BLACK	0.3	4.5	0.9	3.9

RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2025	Peter
Approved	03.03.2025	Peter
Modification	Date	Name



Date	Name	Description: Wire to Board Wafer Pitch 2.54mm 4Pin Straight SMT	
		ASSMANN WSW-NO.	
		A-WBP-M005EG-04SR1	
Drawing-No.		ASS 10022 CO	rev00
Customer-No.		Sheet 7 / 26	

1

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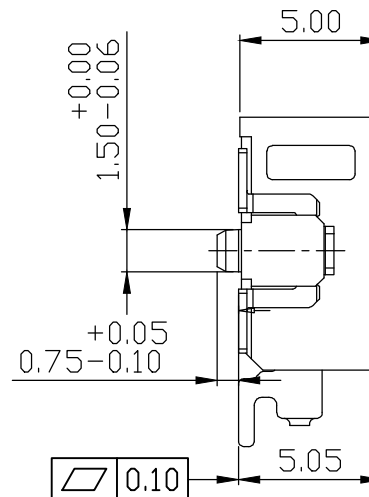
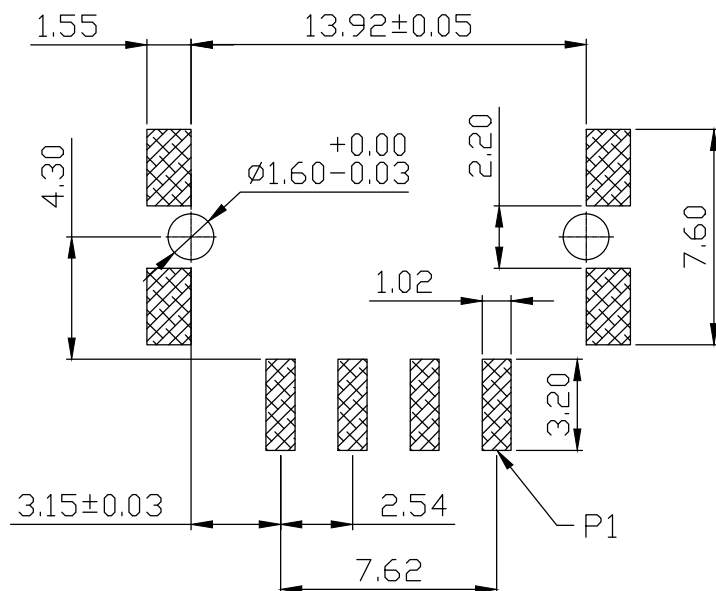
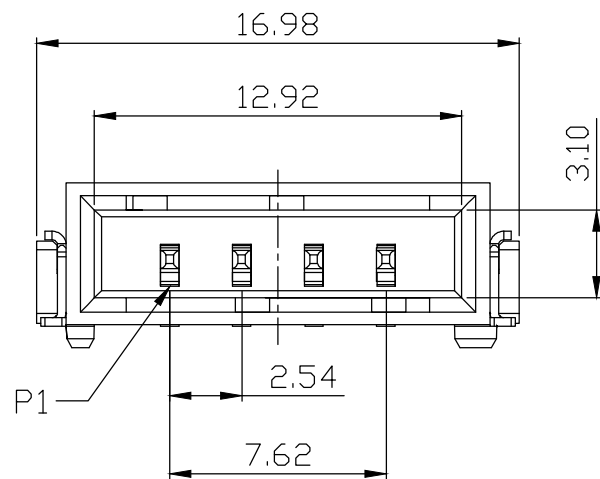
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A



NOTE:

1.MATERIAL:

- 1.1 Insulator:LCP,UL94V-0,Black
- 1.2 Contact:Copper Alloy

2. FINISH

- 2.1 Contact: Au 15u" over nickel on contact area, Matte Tin over Nickel on solder area

3.ELECTRICAL

- 3.1 Current Rating:12A Max.
- 3.2 Contact Resistance:20mΩ Max.
- 3.3 Withstand Voltage:2000V AC
- 3.4 Insulation Resistance:1000 MΩ min

- 4.Operating temperature:-55°C TO +150°C
- 5.Soldering temperature:260±5 °C for 3-5S
- 6.Packing: Tape Reel

A

B

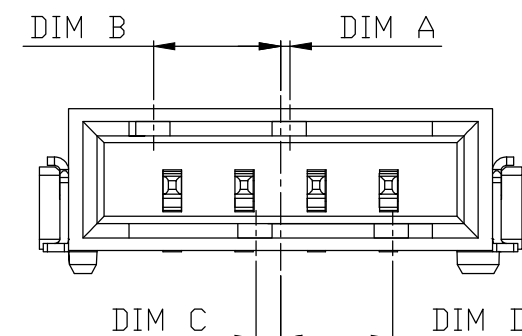
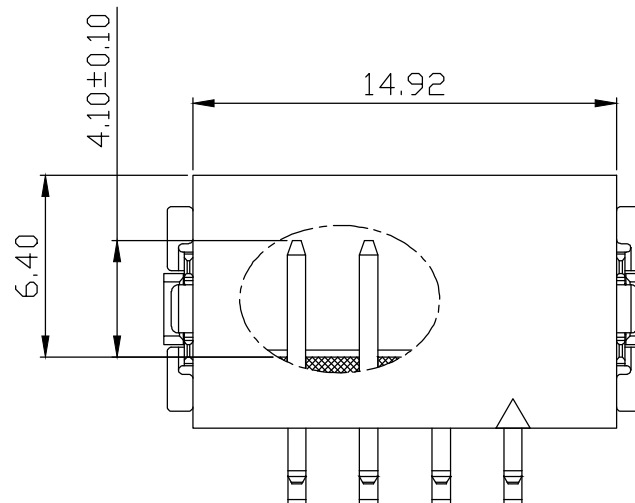
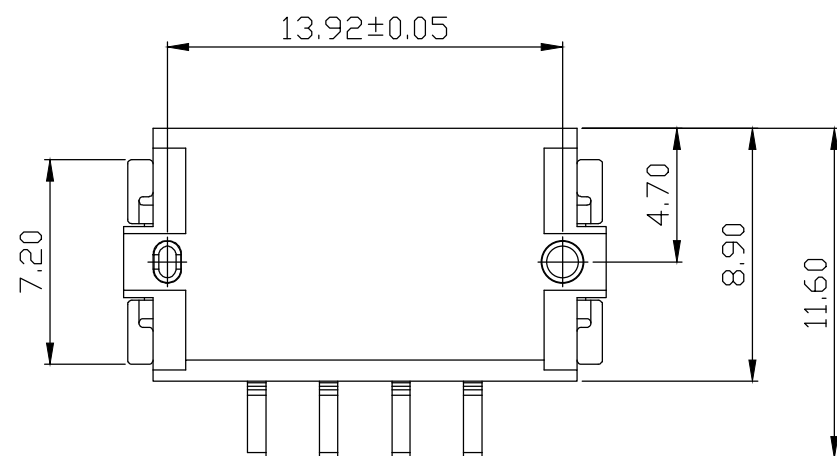
C

D

E

F

D



D

E

F

F

COLOR	DIMENSION			
	DIM A	DIM B	DIM C	DIM D
BLACK	0.3	4.5	0.9	3.9

G

RoHS compliant

unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2024	Peter
Modification	Date	Name



Date
Name
Description: Wire to Board Wafer 4Pin
Pitch 2.54mm Right Angle SMT
Drawn 03.03.2025 Peter
Approved 03.03.2025 Peter
ASSMANN WSW-NO.
A-WBP-M005EA-04SR1

Drawing-No.
ASS 10022 CO rev00
Customer-No.
Sheet 8 / 26

G

H

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A

A

B

B

C

C

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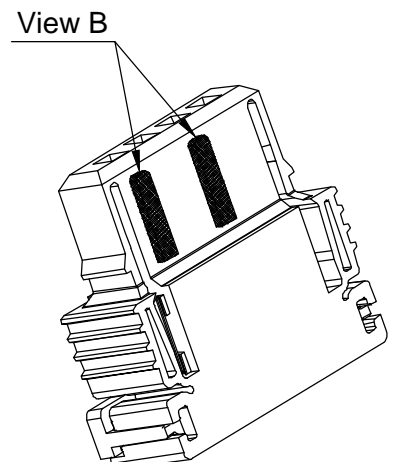
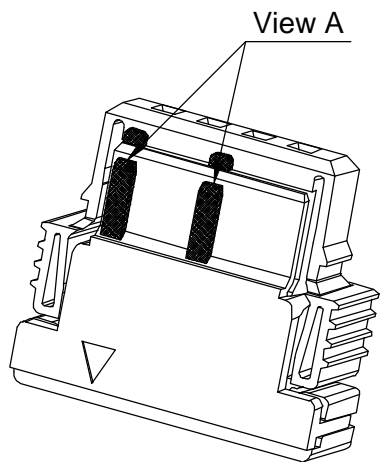
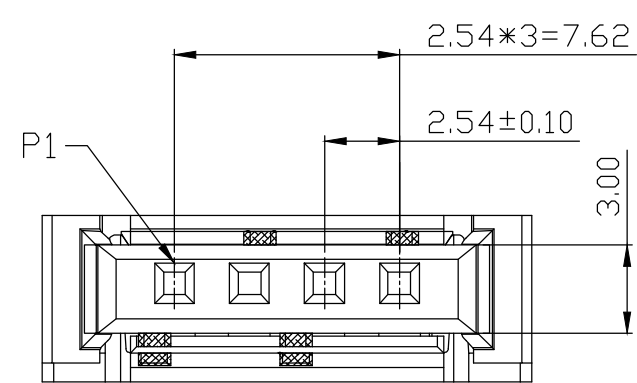
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F

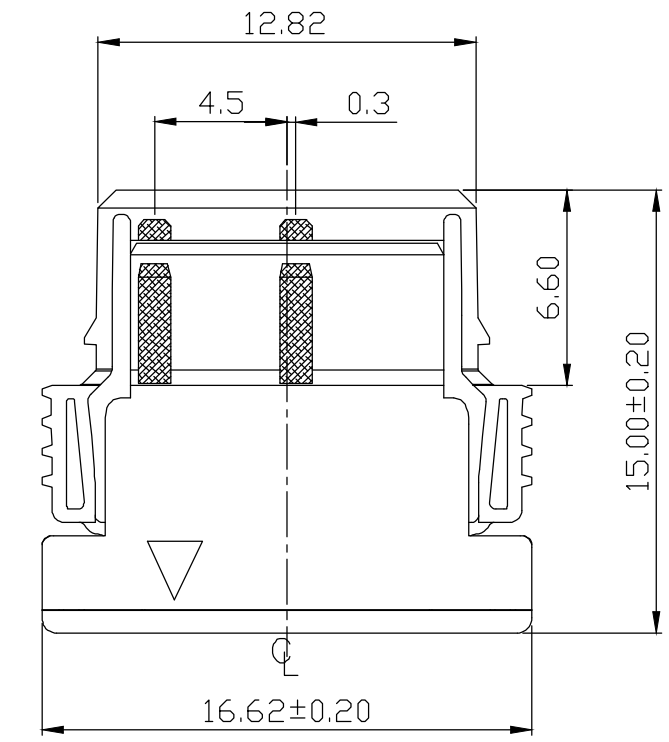


NOTE:

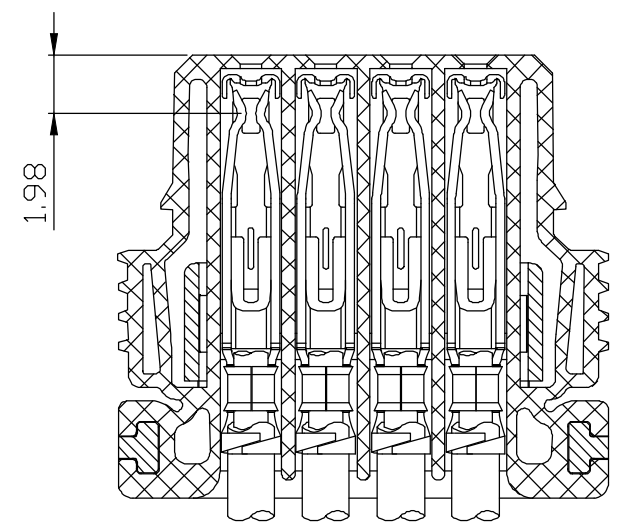
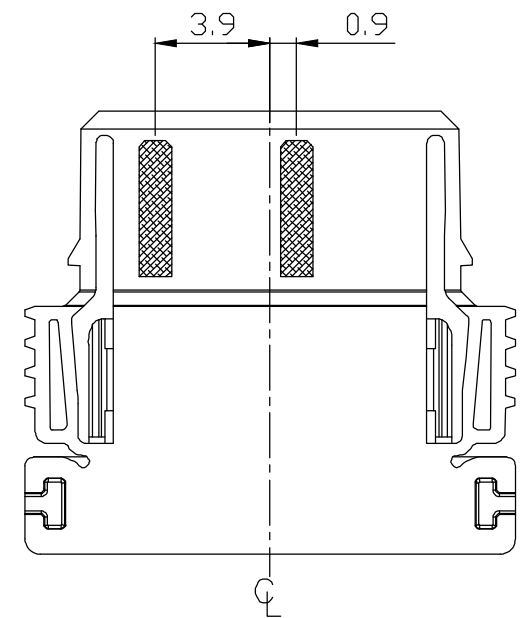
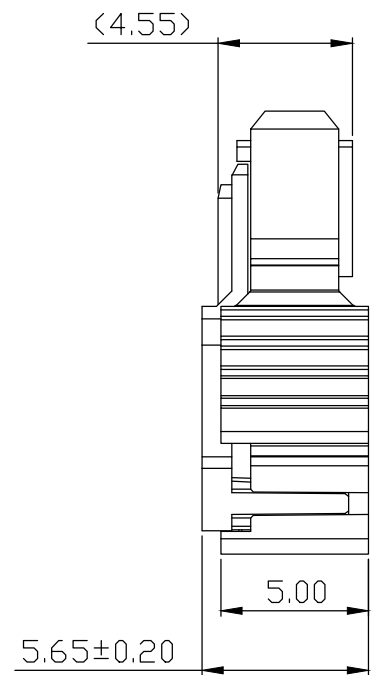
1.MATERIAL:
1.1 Housing:PA46,UL94V-0,Black

2.ELECTRICAL
2.1 Withstand Voltage:2000V AC
2.2 Insulation Resistance:1000 MΩ min

3.Operating temperature:-55°C TO +125°C
4.Packing:Tray



Fool Proof Diagram



Terminal Diagram

G

G

RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2025		
Approved	03.03.2025		
Modification	Date	Name	

Date

Name

Drawn 03.03.2025 Peter

Approved 03.03.2025 Peter

ASSMANN
WSW components
A company of BCS

Description: Wire to Board Housing Pitch 2.54mm 4Pin	
ASSMANN WSW-NO. A-WBH-M005EG-04CP1	
Drawing-No. ASS 10022 CO	rev00
Customer-No.	Sheet 9 / 26

H

H

1

2

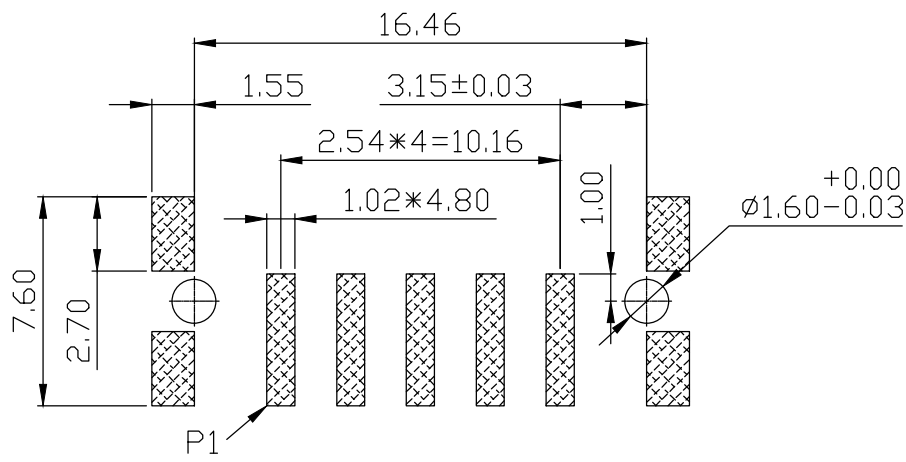
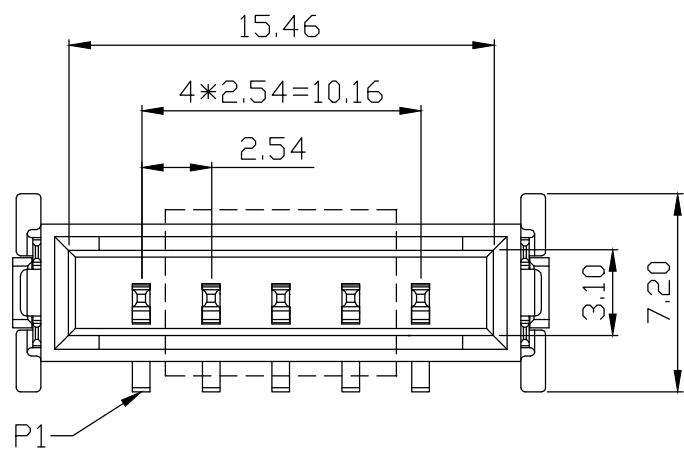
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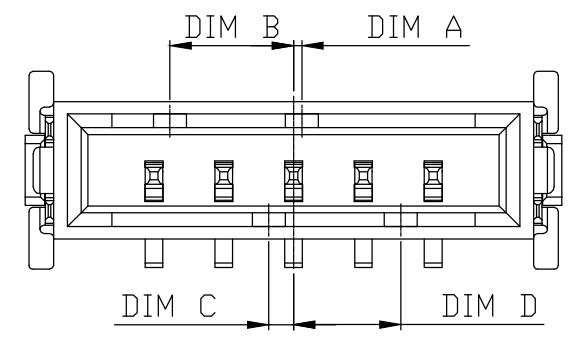
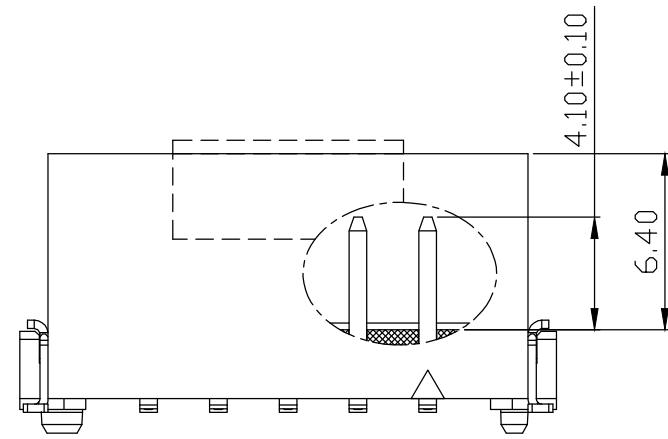
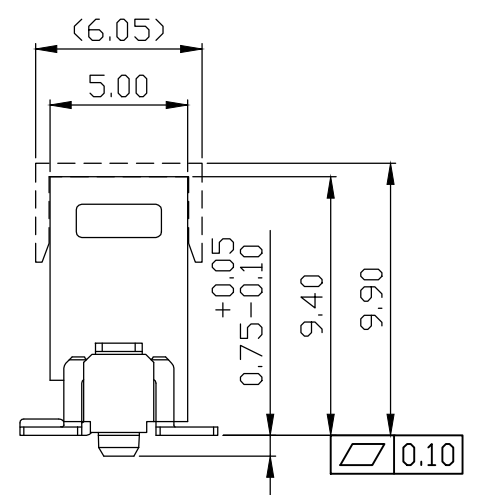
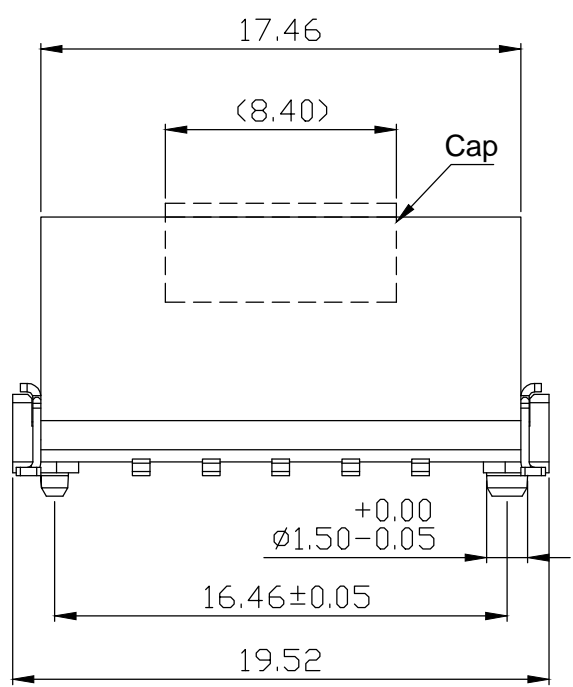
7



RECOMMENDED PCB LAYOUT(TOP VIEW)
PCB BOARD TOLERANCE:±0.05

NOTE:

- MATERIAL:**
 - 1.1 Insulator:LCP,UL94V-0,Black
 - 1.2 Contact:Copper Alloy
- FINISH**
 - 2.1 Contact: Au 15u" over nickel on contact area, Matte Tin over Nickel on solder area
- ELECTRICAL**
 - 3.1 Current Rating:12A Max.
 - 3.2 Contact Resistance:20mΩ Max.
 - 3.3 Withstand Voltage:2000V AC
 - 3.4 Insulation Resistance:1000 MΩ min
- 4.Operating temperature:-55°C TO +150°C
- 5.Soldering temperature:260°C for 3~5S
- 6.Packing: Tape Reel+Cap



COLOR	DIMENSION			
	DIM A	DIM B	DIM C	DIM D
BLACK	0.3	4.5	0.9	3.9

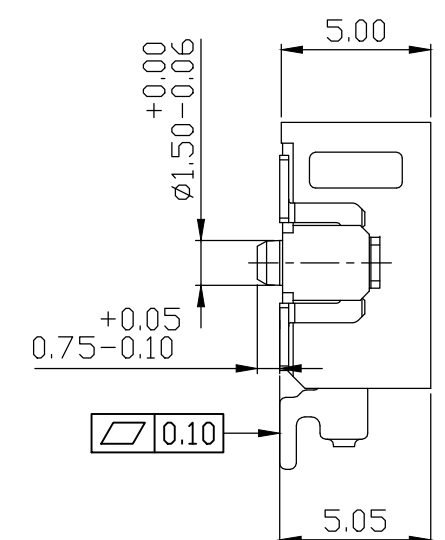
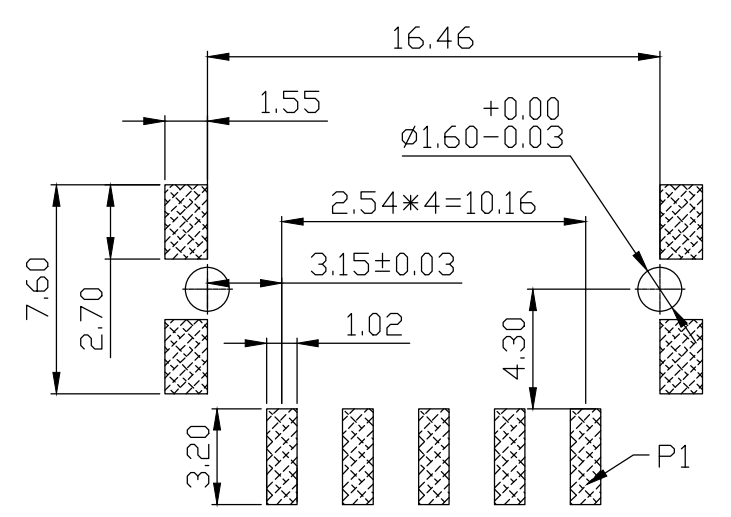
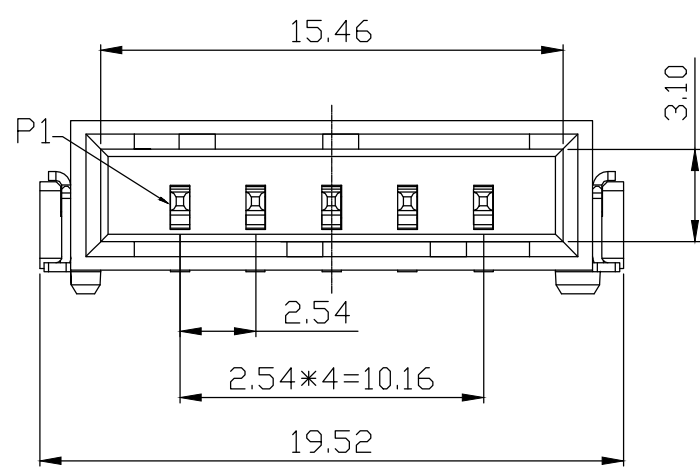
RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2025	Peter	Date	Name
Approved	03.03.2025	Peter		
Id.	Modification	Date	Name	



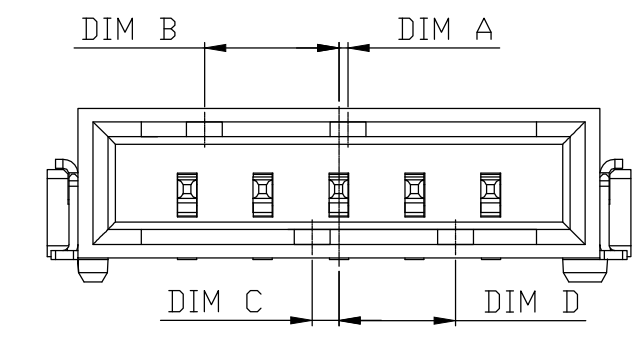
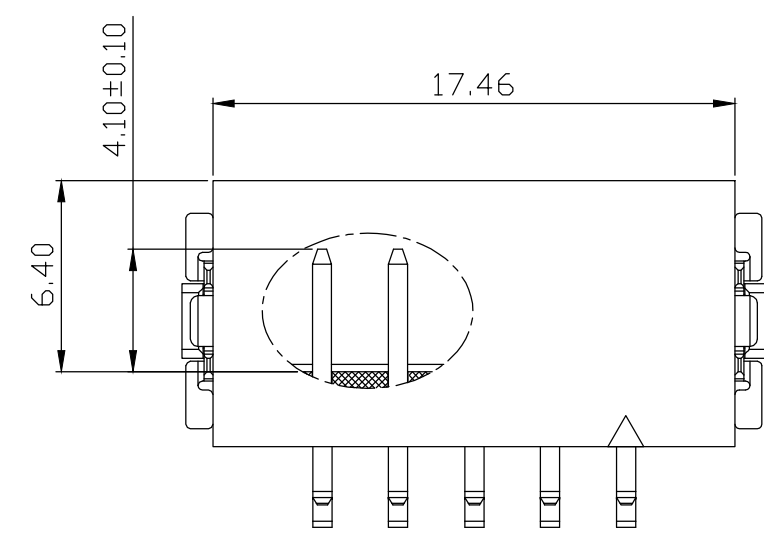
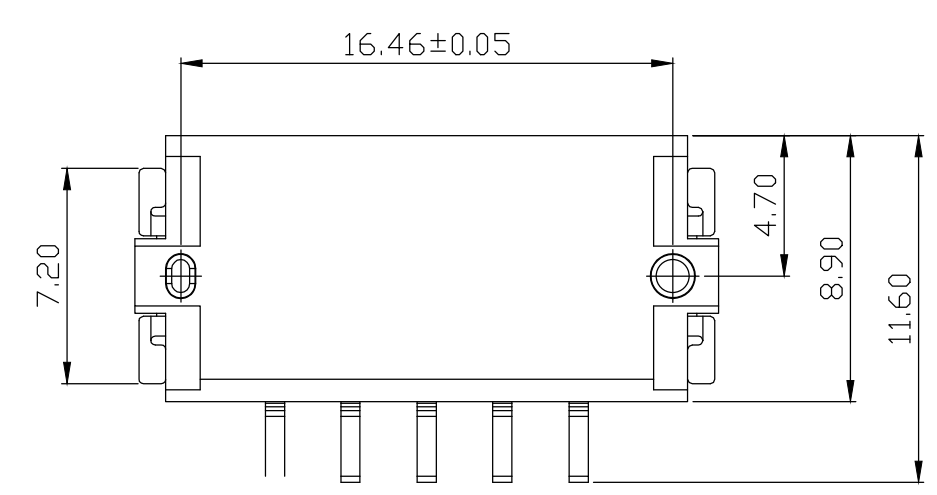
Description: Wire to Board Wafer Pitch 2.54mm 5Pin Straight SMT	
ASSMANN WSW-NO. A-WBP-M005EG-05SR1	
Drawing-No. ASS 10022 CO	rev00
Customer-No.	Sheet 10 / 26



NOTE:

- MATERIAL:**
 - 1.1 Insulator: LCP, UL94V-0, Black
 - 1.2 Contact: Copper Alloy
- FINISH**
 - 2.1 Contact: Au 15u" over nickel on contact area, Matte Tin over Nickel on solder area
- ELECTRICAL**
 - 3.1 Current Rating: 12A Max.
 - 3.2 Contact Resistance: 20mΩ Max.
 - 3.3 Withstand Voltage: 2000V AC
 - 3.4 Insulation Resistance: 1000 MΩ min
4. Operating temperature: -55°C TO +150°C
5. Soldering temperature: 260°C for 3~5S
6. Packing: Tape Reel

RECOMMENDED PCB LAYOUT(TOP VIEW)
PCB BOARD TOLERANCE: ±0.05



COLOR	DIMENSION			
	DIM A	DIM B	DIM C	DIM D
BLACK	0.3	4.5	0.9	3.9

RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2025	Peter	Date	Name
Approved	03.03.2025	Peter		
Modification	Date	Name		



Description: Wire to Board Wafer Pitch 2.54mm 5Pin R/A SMT	
ASSMANN WSW-NO. A-WBP-M005EA-05SR1	
Drawing-No. ASS 10022 CO	rev00
Customer-No.	Sheet 11 / 26

1

2

3

4

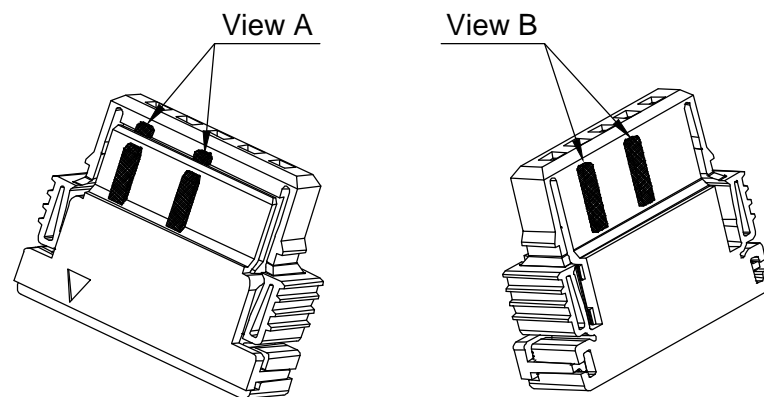
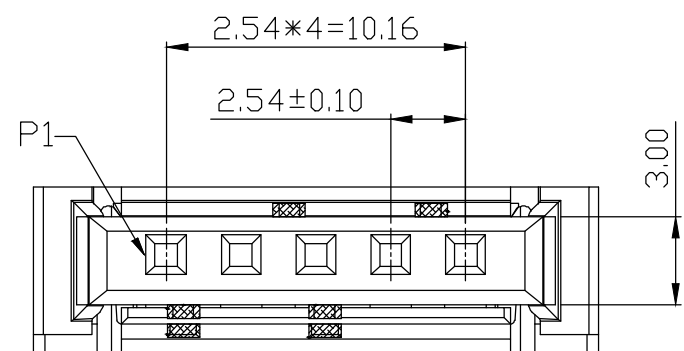
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A

A



NOTE:

- 1.MATERIAL:
 - 1.1 Housing:PA46,UL94V-0,Black
- 2.ELECTRICAL
 - 2.1 Withstand Voltage:2000V AC
 - 2.2 Insulation Resistance:1000 MΩ min
- 3.Operating temperature:-55°C TO +125°C
- 4.Packing:Tray

B

B

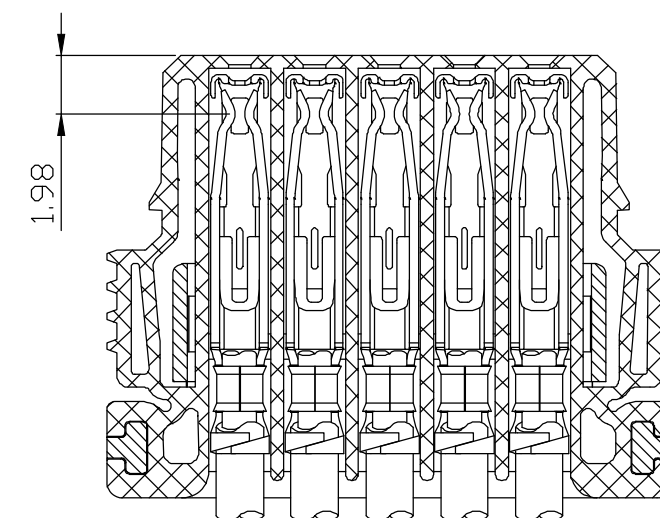
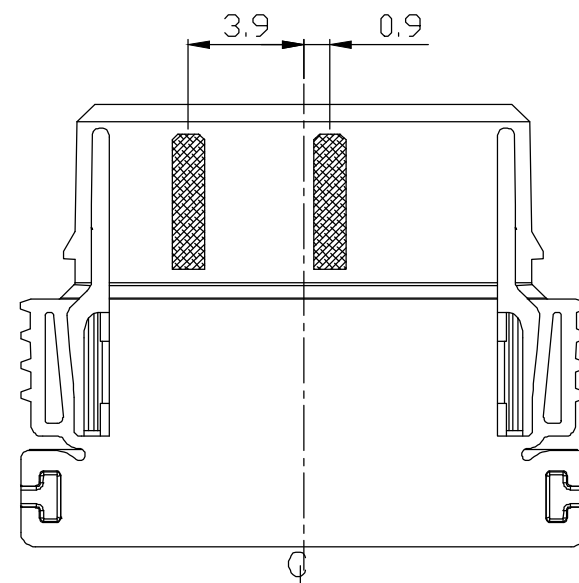
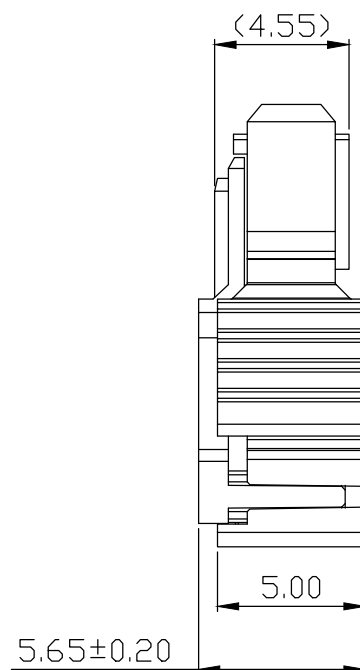
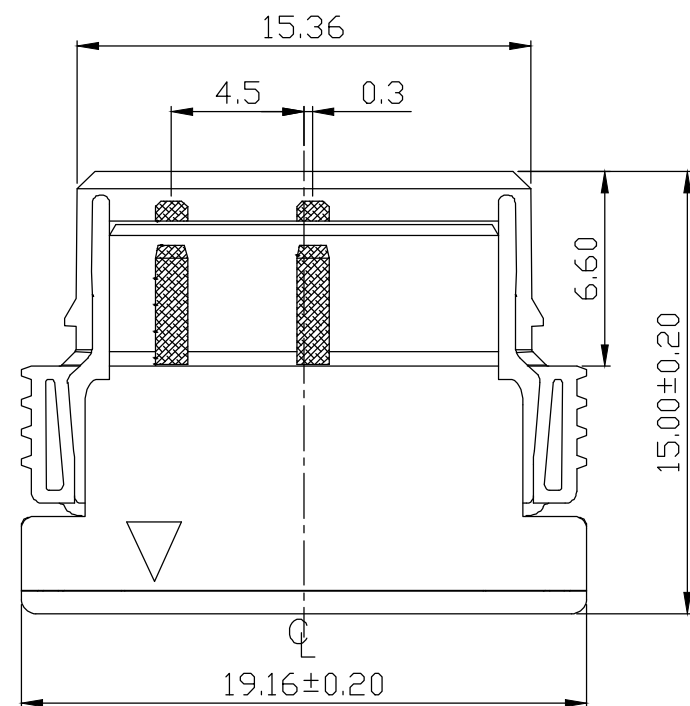
C

C

Fool Proof Diagram

D

D



Terminal Diagram

E

E

F

F

G

G

RoHS compliant

unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2025		
Modification	Date	Name	

Date: 03.03.2025
 Name: Peter
 Description: Wire to Board Housing
 Pitch 2.54mm 5Pin
 ASSMANN WSW-NO.
A-WBH-M005EG-05CP1
 Drawing-No. ASS 10022 CO rev00
 Customer-No. Sheet 12 / 26

ASSMANN
 WSW components
 A company of BCS

H

H

1

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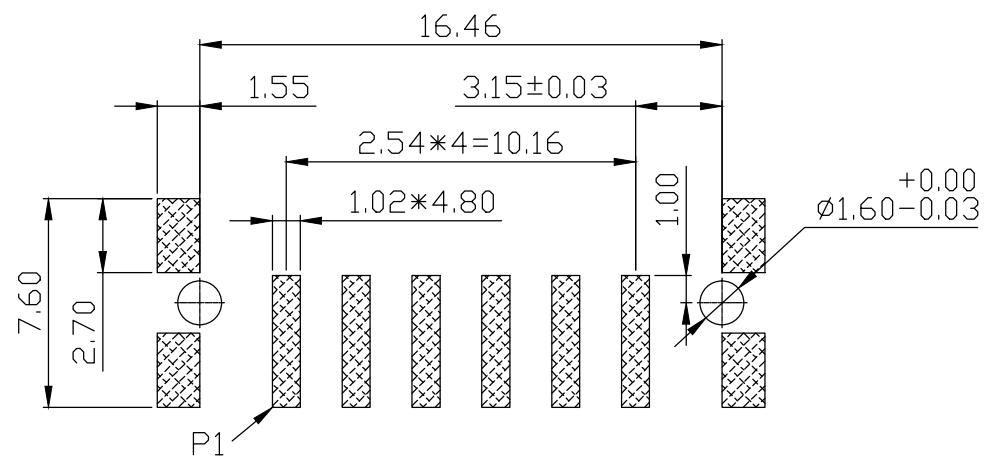
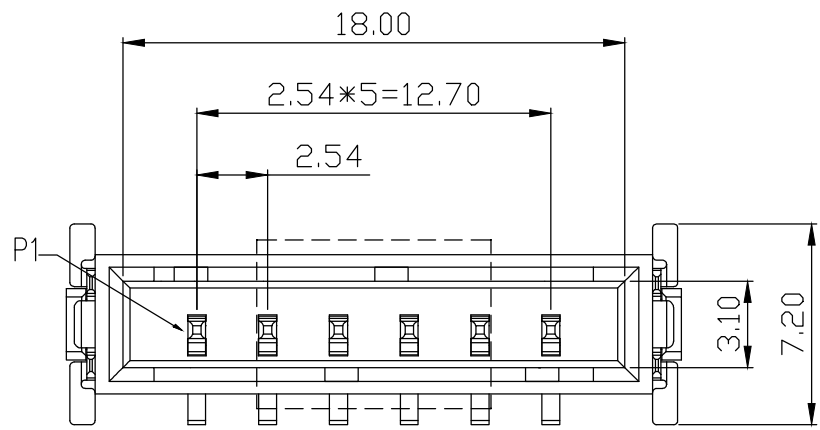
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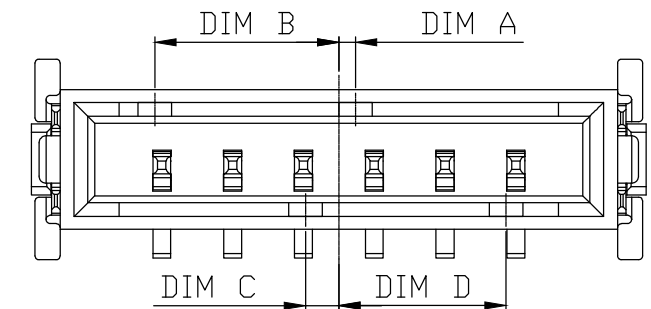
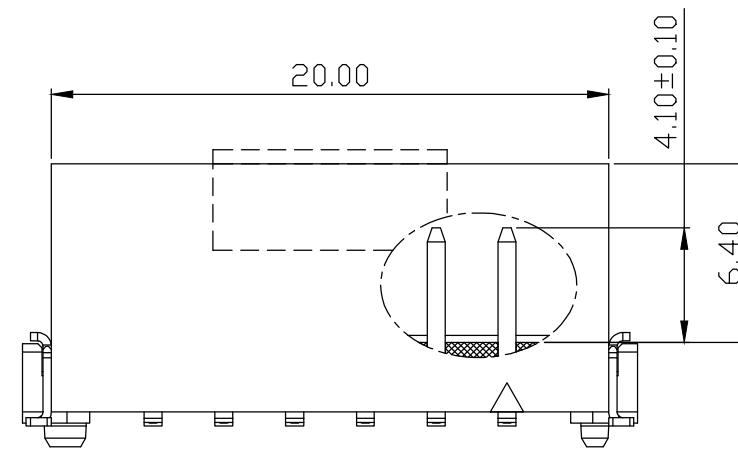
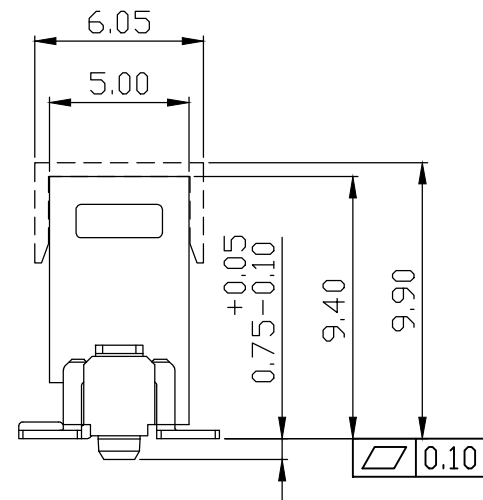
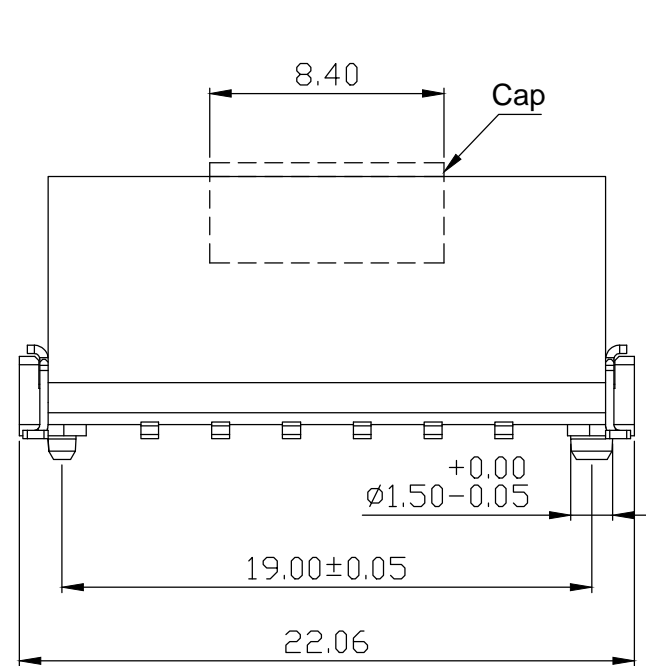
7



RECOMMENDED PCB LAYOUT(TOP VIEW)
PCB BOARD TOLERANCE:±0.05

NOTE:

- 1.MATERIAL:
 - 1.1 Insulator:LCP,UL94V-0,Black
 - 1.2 Contact:Copper Alloy
2. FINISH
 - 2.1 Contact: Au 15u" over nickel on contact area, Matte Tin over Nickel on solder area
- 3.ELECTRICAL
 - 3.1 Current Rating:12A Max.
 - 3.2 Contact Resistance:20mΩ Max.
 - 3.3 Withstand Voltage:2000V AC
 - 3.4 Insulation Resistance:1000 MΩ min
- 4.Operating temperature:-55°C TO +150°C
- 5.Soldering temperature:260°C for 3~5S
- 6.Packing: Tape Reel+Cap



COLOR	DIMENSION			
	DIM A	DIM B	DIM C	DIM D
BLACK	0.6	6.6	1.2	6.0

RoHS compliant
unit:mm

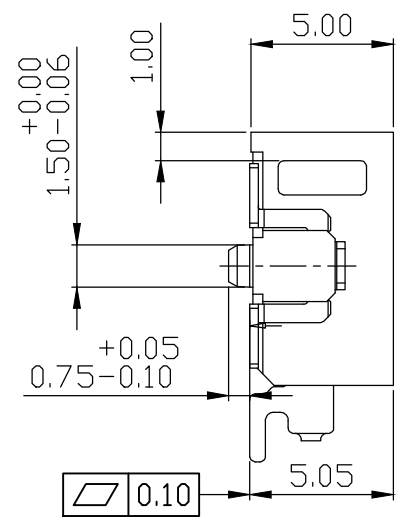
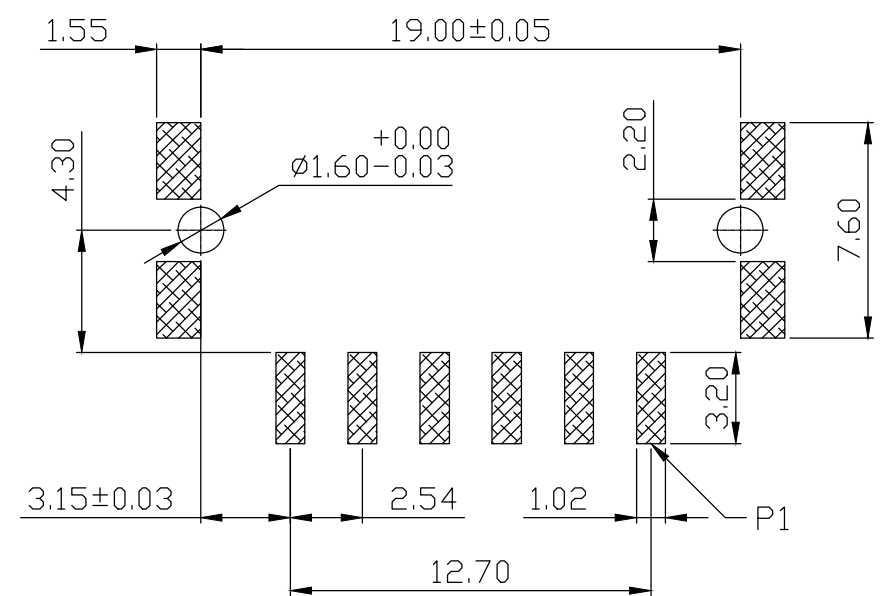
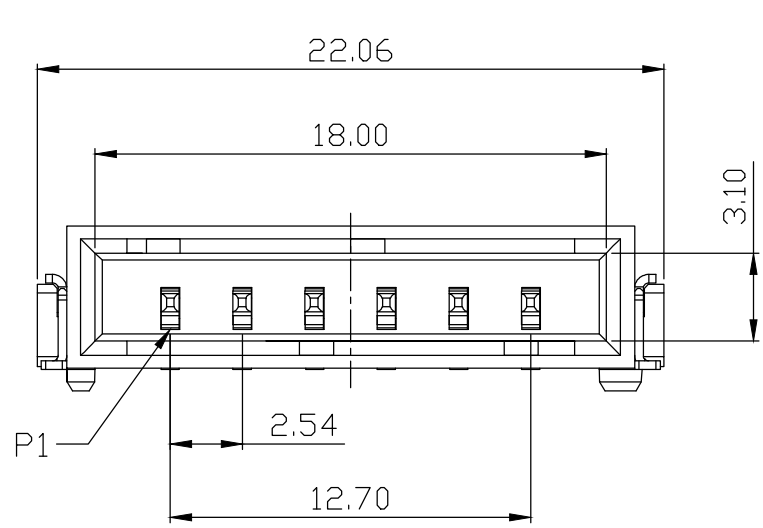
Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

			Date	Name	Description: Wire to Board Wafer Pitch 2.54mm 6Pin Straight SMT	
		Drawn	03.03.2025	Peter		
		Approved	03.03.2025	Peter		
					ASSMANN WSW-NO.	
					A-WBP-M005EG-06SR1	
					Drawing-No.	
					ASS 10022 CO	rev00
					Customer-No.	Sheet
						13 / 26



Drawn	03.03.2025	Peter
Modification	Date	Name

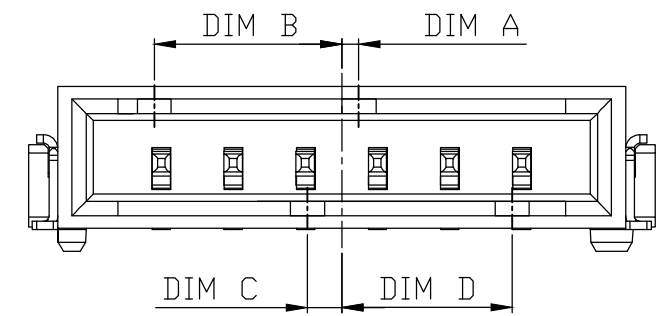
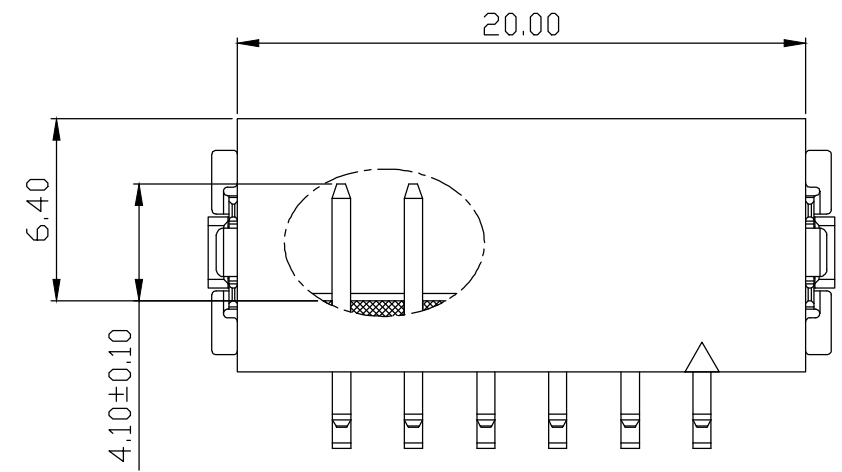
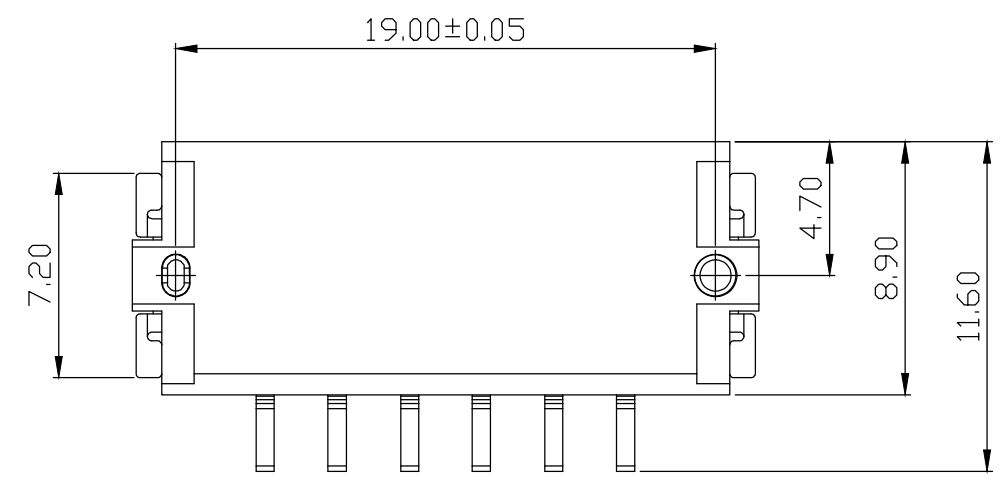
Drawing-No.	ASS 10022 CO	rev00
Customer-No.		Sheet
		13 / 26



NOTE:

- MATERIAL:**
 - 1.1 Insulator: LCP, UL94V-0, Black
 - 1.2 Contact: Copper Alloy
- FINISH**
 - 2.1 Contact: Au 15u" over nickel on contact area, Matte Tin over Nickel on solder area
- ELECTRICAL**
 - 3.1 Current Rating: 12A Max.
 - 3.2 Contact Resistance: 20mΩ Max.
 - 3.3 Withstand Voltage: 2000V AC
 - 3.4 Insulation Resistance: 1000 MΩ min
4. Operating temperature: -55°C TO +150°C
5. Soldering temperature: 260±5 °C for 3-5S
6. Packing: Tape Reel

RECOMMENDED PCB LAYOUT (TOP VIEW)
PCB BOARD TOLERANCE: ±0.05



COLOR	DIMENSION			
	DIM A	DIM B	DIM C	DIM D
BLACK	0.6	6.6	1.2	6.0

RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2025	Peter
Modification	Date	Name



Date	Name	Description: Wire to Board Wafer 6Pin Pitch 2.54mm Right Angle SMT
03.03.2025	Peter	
Approved	03.03.2025	ASSMANN WSW-NO.
		A-WBP-M005EA-06SR1
Drawing-No.		rev00
ASS 10022 CO		
Customer-No.		Sheet
		14 / 26

1

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7

A

A

B

B

C

C

D

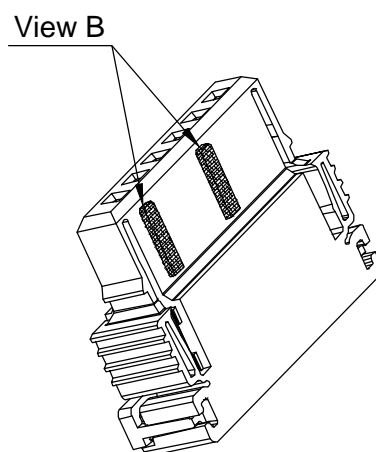
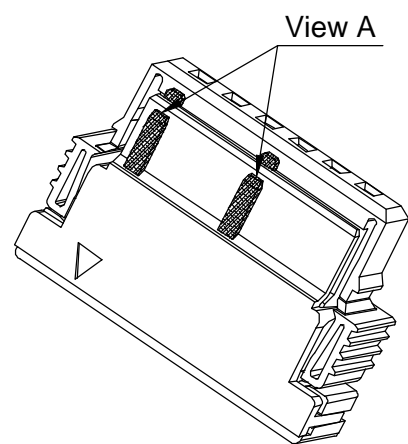
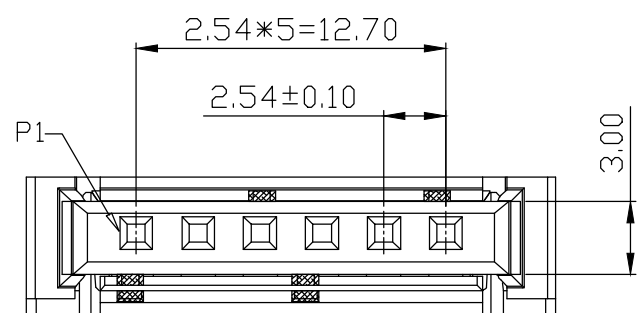
D

E

E

F

F



NOTE:

1.MATERIAL:

1.1 Housing:PA46,UL94V-0,Black

2.ELECTRICAL

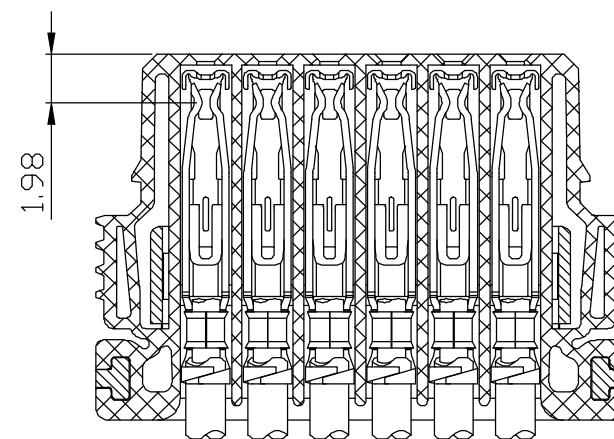
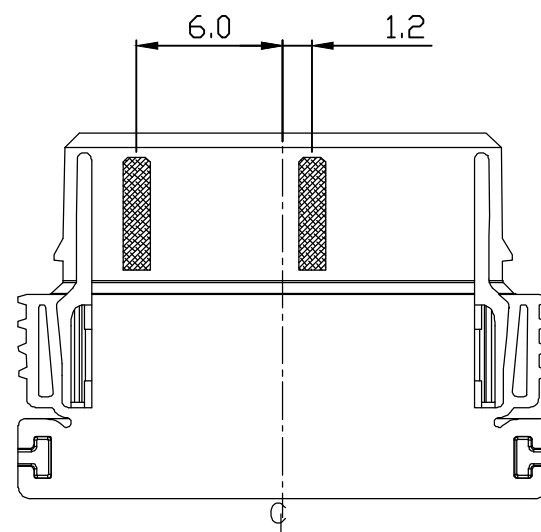
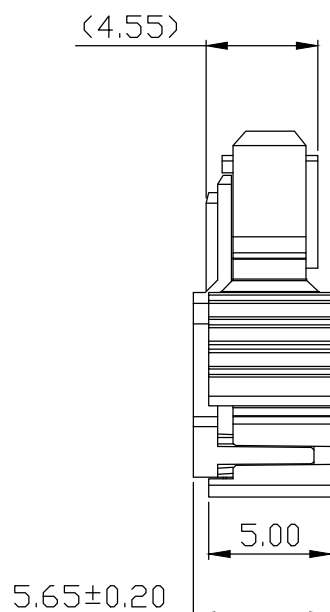
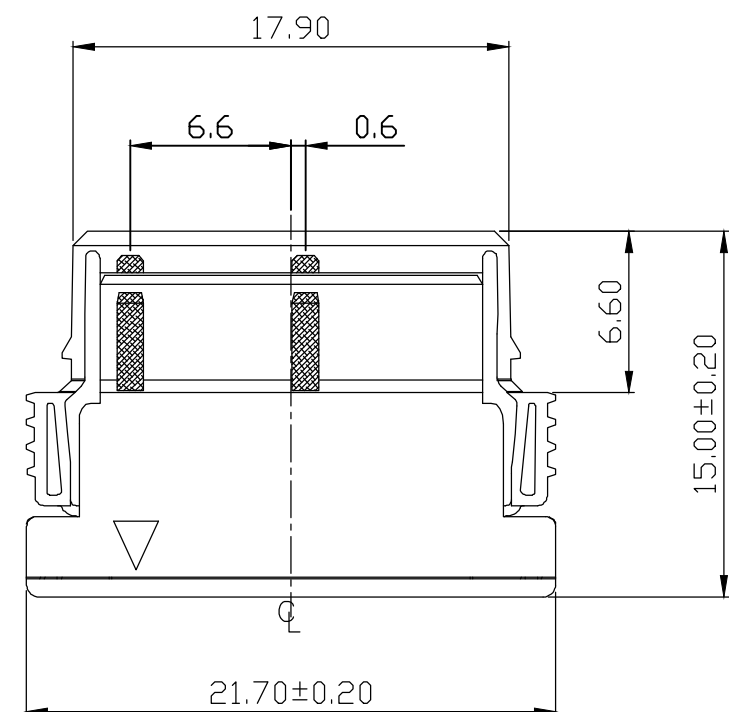
2.1 Withstand Voltage:2000V AC

2.2 Insulation Resistance:1000 MΩ min

3.Operating temperature:-55°C TO +125°C

4.Packing:Tray

Fool Proof Diagram



Terminal Diagram

G

G

RoHS compliant

unit:mm

Scale Free

TOLERANCE

.X ±0.40

.XX ±0.25

.XXX ±0.15

DIM TOL

X.° ±3°

Angle TOL

ⓐ

Drawn

03.03.2025

Peter

Id.

Modification

Date

Name

Date

Name

Description: Wire to Board Housing
Pitch 2.54mm 6Pin

Drawn

03.03.2025

Peter

Approved

03.03.2025

Peter

ASSMANN WSW-NO.

A-WBH-M005EG-06CP1

Drawing-No.

ASS 10022 CO

rev00

Customer-No.

Sheet
15/ 26

H

H



1

2

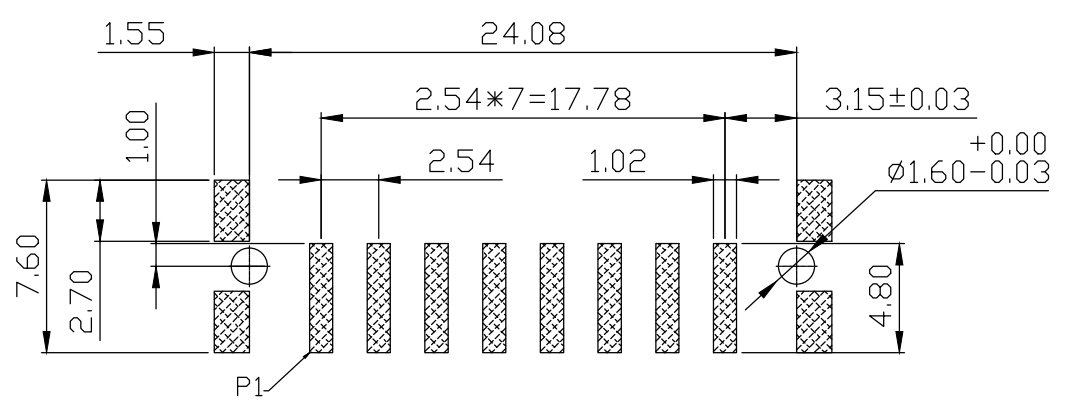
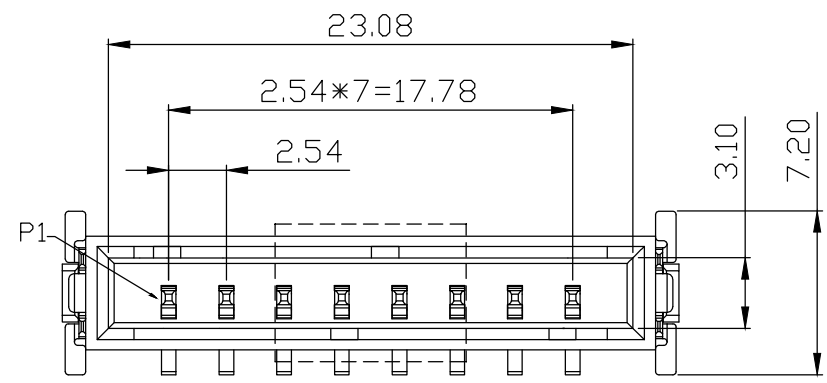
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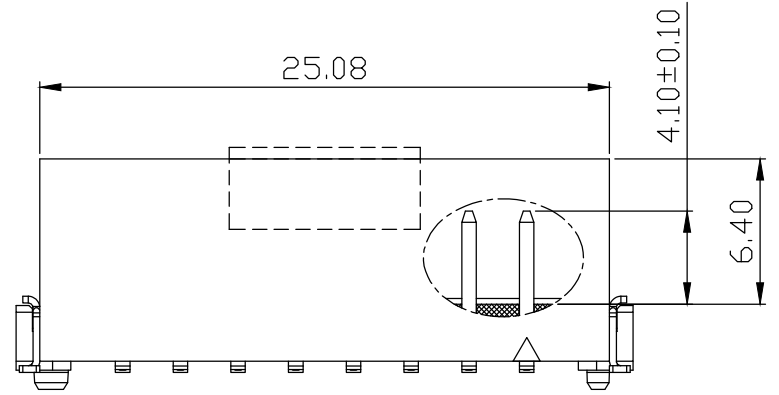
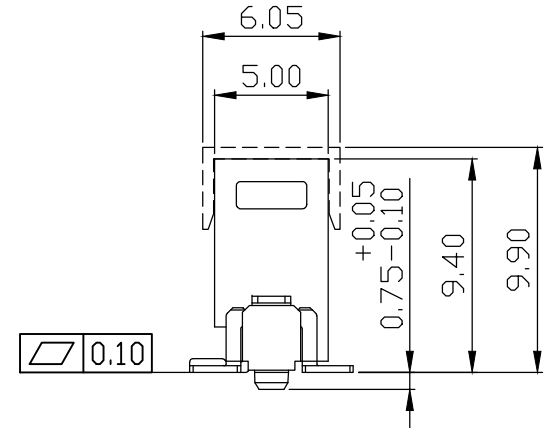
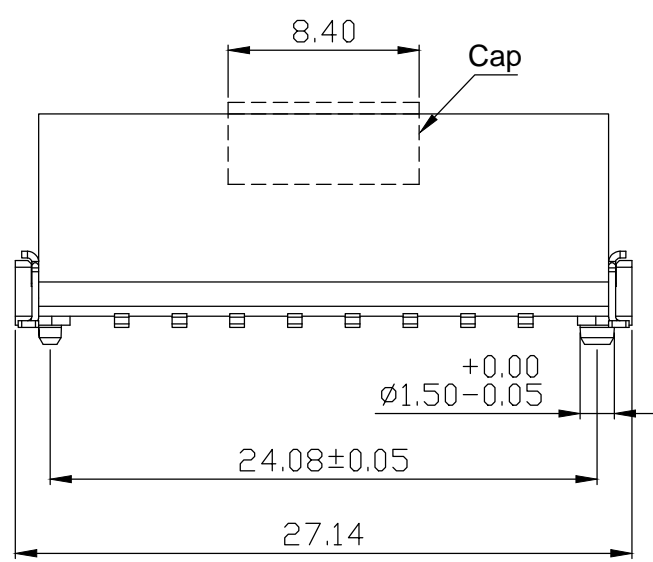
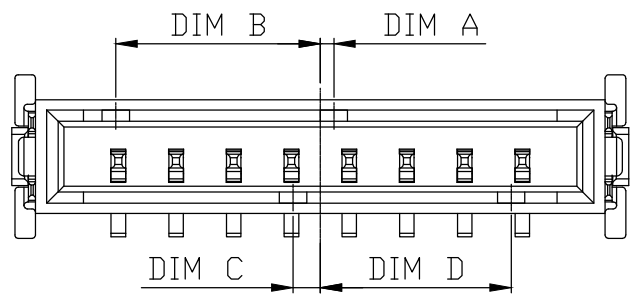
7



NOTE:

- MATERIAL:**
 - 1.1 Insulator:LCP,UL94V-0,Black
 - 1.2 Contact:Copper Alloy
- FINISH**
 - 2.1 Contact: Au 15u" over nickel on contact area, Matte Tin over Nickel on solder area
- ELECTRICAL**
 - 3.1 Current Rating:12A Max.
 - 3.2 Contact Resistance:20mΩ Max.
 - 3.3 Withstand Voltage:2000V AC
 - 3.4 Insulation Resistance:1000 MΩ min
4. Operating temperature:-55°C TO +150°C
5. Soldering temperature:260°C for 3~5S
6. Packing: Tape Reel+Cap

RECOMMENDED PCB LAYOUT(TOP VIEW)
PCB BOARD TOLERANCE:±0.05



COLOR	DIMENSION			
	DIM A	DIM B	DIM C	DIM D
BLACK	0.6	9.0	1.2	8.4

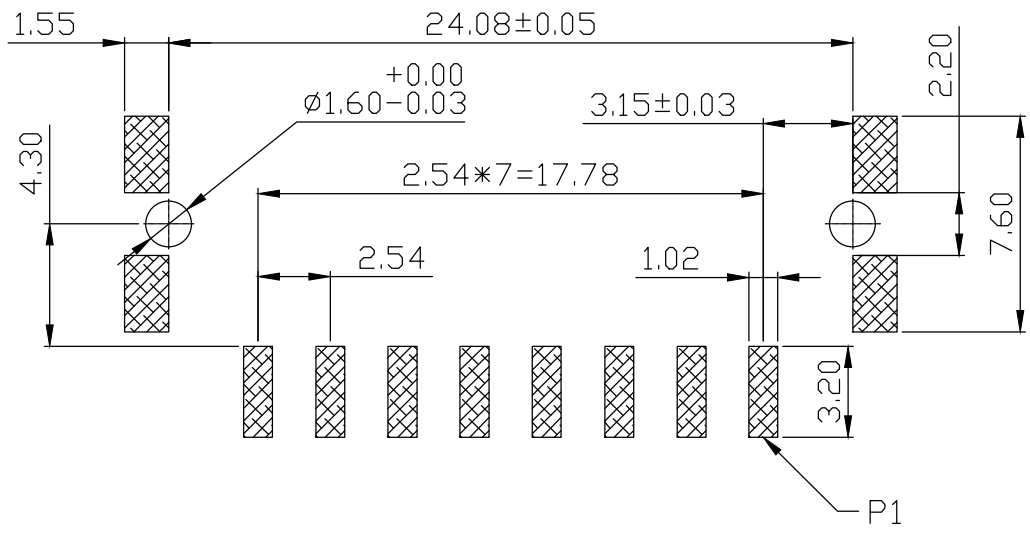
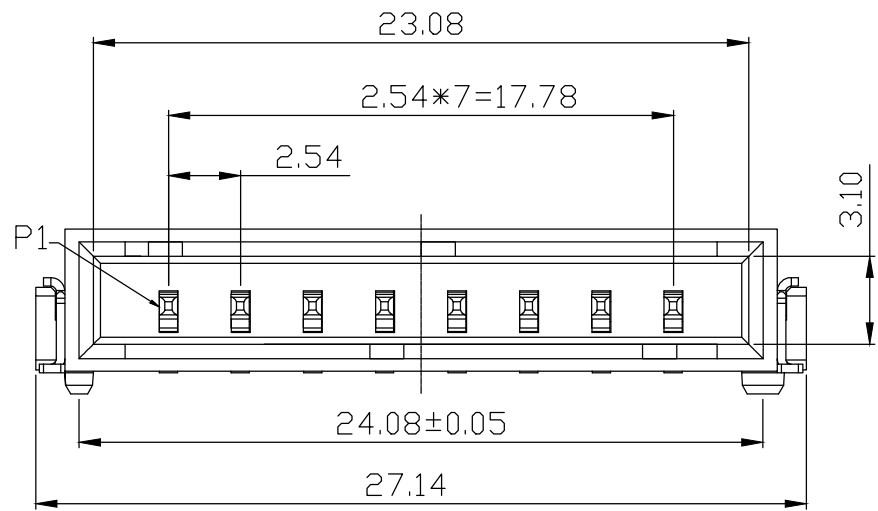
RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2025	Peter
Approved	03.03.2025	Peter
Modification	Date	Name



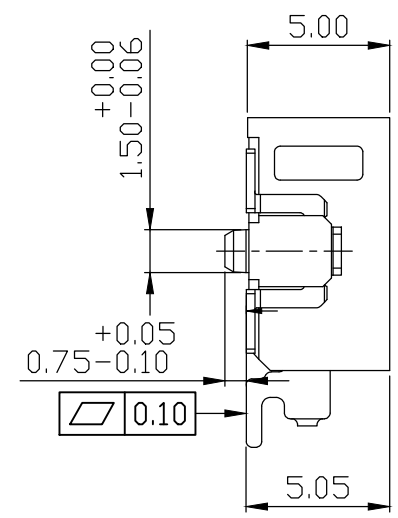
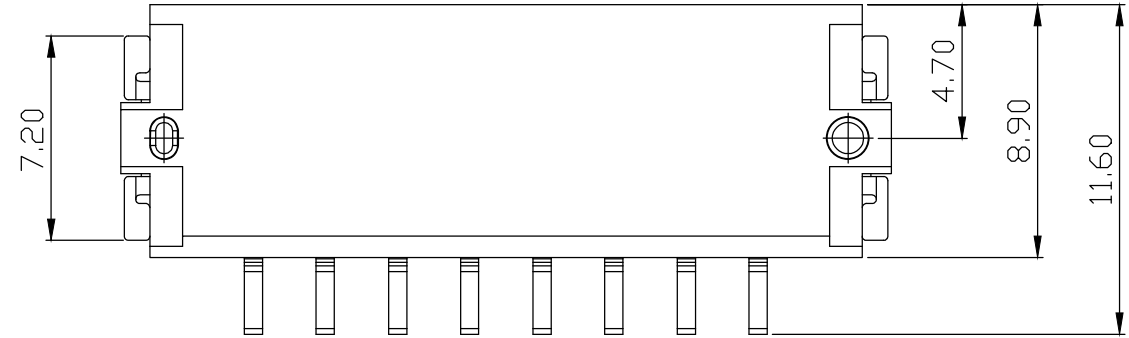
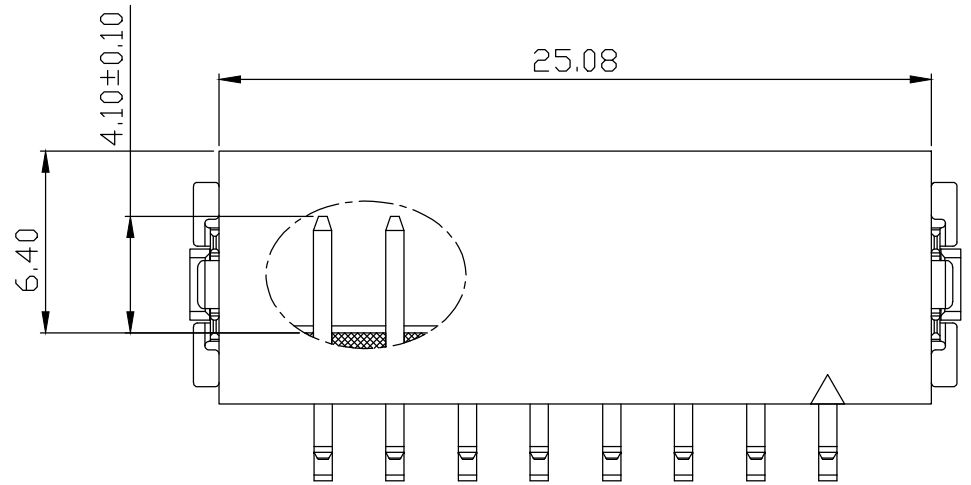
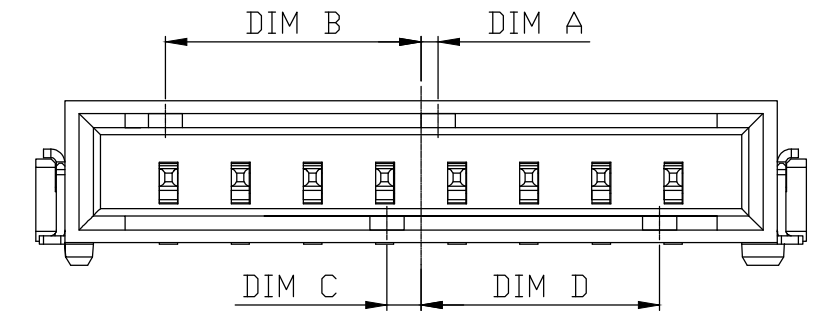
Date	Name	Description: Wire to Board Wafer Pitch 2.54mm 8Pin Straight SMT	
		ASSMANN WSW-NO. A-WBP-M005EG-08SR1	
Drawing-No.		ASS 10022 CO	rev00
Customer-No.		Sheet 16 / 26	



NOTE:

- MATERIAL:**
 - 1.1 Insulator:LCP,UL94V-0,Black
 - 1.2 Contact:Copper Alloy
- FINISH**
 - 2.1 Contact: Au 15u" over nickel on contact area, Matte Tin over Nickel on solder area
- ELECTRICAL**
 - 3.1 Current Rating:12A Max.
 - 3.2 Contact Resistance:20mΩ Max.
 - 3.3 Withstand Voltage:2000V AC
 - 3.4 Insulation Resistance:1000 MΩ min
4. Operating temperature:-55°C TO +150°C
5. Soldering temperature:260°C for 3~5S
6. Packing: Tape Reel+Cap

RECOMMENDED PCB LAYOUT(TOP VIEW)
PCB BOARD TOLERANCE:±0.05



COLOR	DIMENSION			
	DIM A	DIM B	DIM C	DIM D
BLACK	0.6	9.0	1.2	8.4

RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2025	Peter
Approved	03.03.2025	Peter
Modification	Date	Name



Date	Name	Description: Wire to Board Wafer Pitch 2.54mm 8Pin R/A SMT	
		ASSMANN WSW-NO. A-WBP-M005EA-08SR1	
Drawing-No.		ASS 10022 CO	rev00
Customer-No.		Sheet 17 / 26	

1

2

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5

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7

A

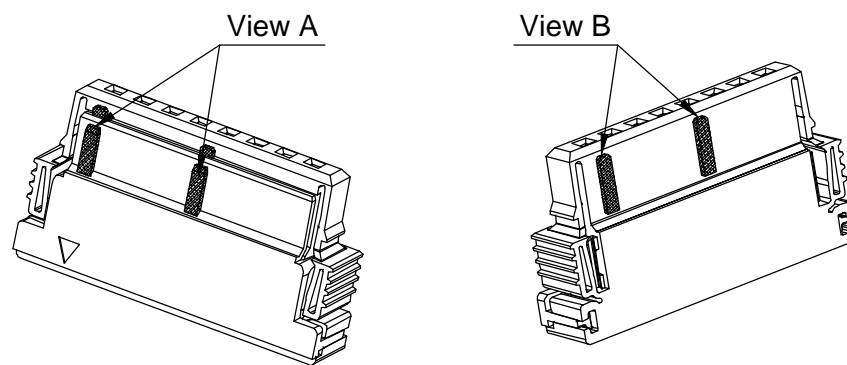
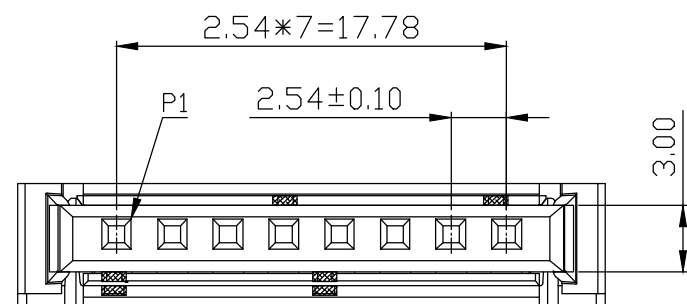
A

NOTE:

1.MATERIAL:
1.1 Housing:PA46,UL94V-0,Black

2.ELECTRICAL
2.1 Withstand Voltage:2000V AC
2.2 Insulation Resistance:1000 MΩ min

3.Operating temperature:-55°C TO +125°C
4.Packing:Tray



Fool Proof Diagram

B

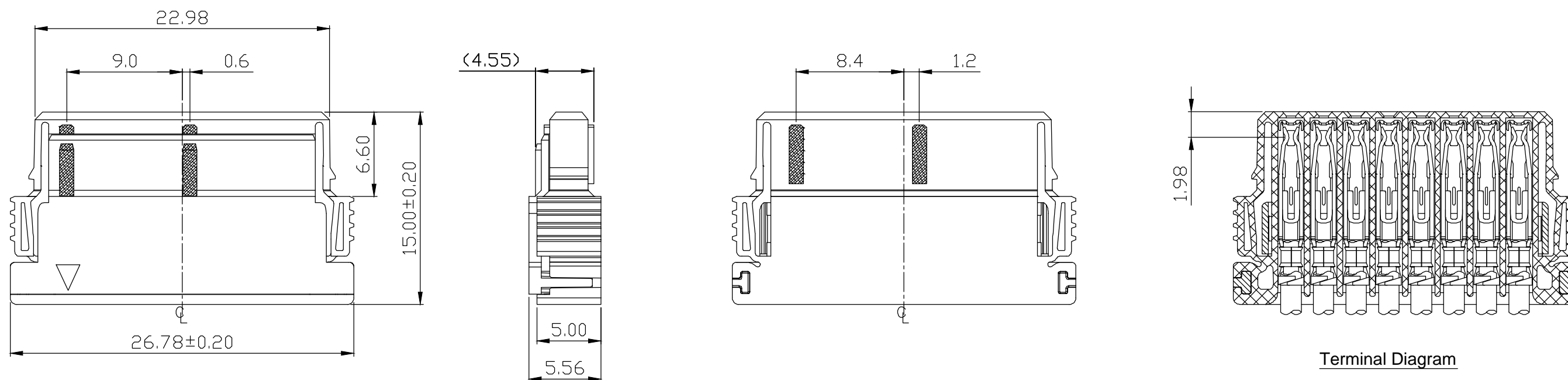
B

C

C

D

D



Terminal Diagram

E

E

F

F

G

G

RoHS compliant

unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2025	Peter
Approved	03.03.2025	Peter
Modification	Date	Name

Date: 03.03.2025
Name: Peter

Drawn: 03.03.2025
Approved: 03.03.2025
Peter

ASSMANN
WSW components
A company of BCS

Description: Wire to Board Housing
Pitch 2.54mm 8Pin

ASSMANN WSW-NO.
A-WBH-M005EG-08CP1

Drawing-No.
ASS 10022 CO rev00

Customer-No.
Sheet 18 / 26

1

2

3

4

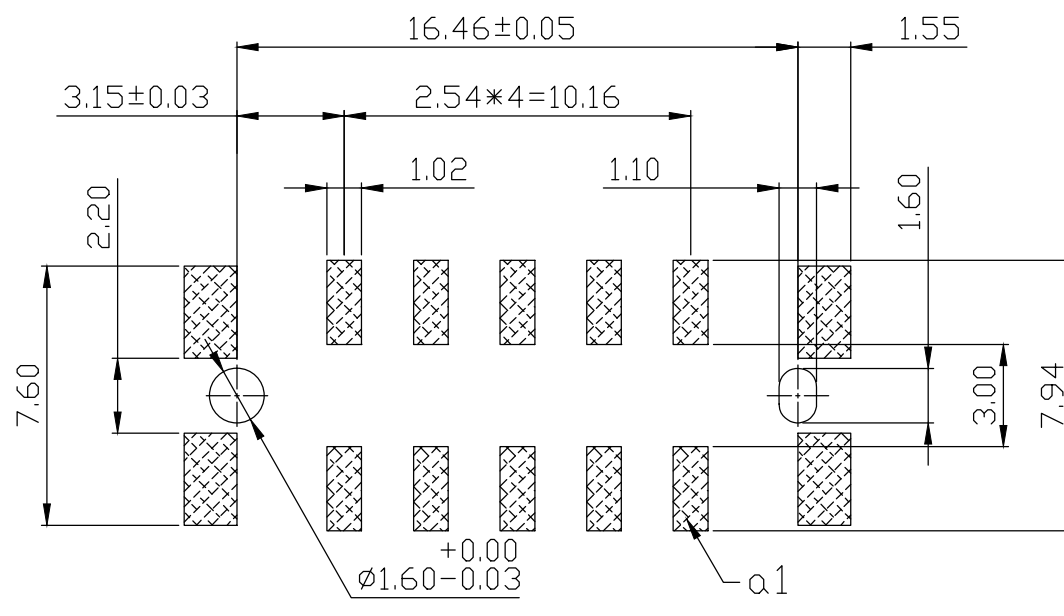
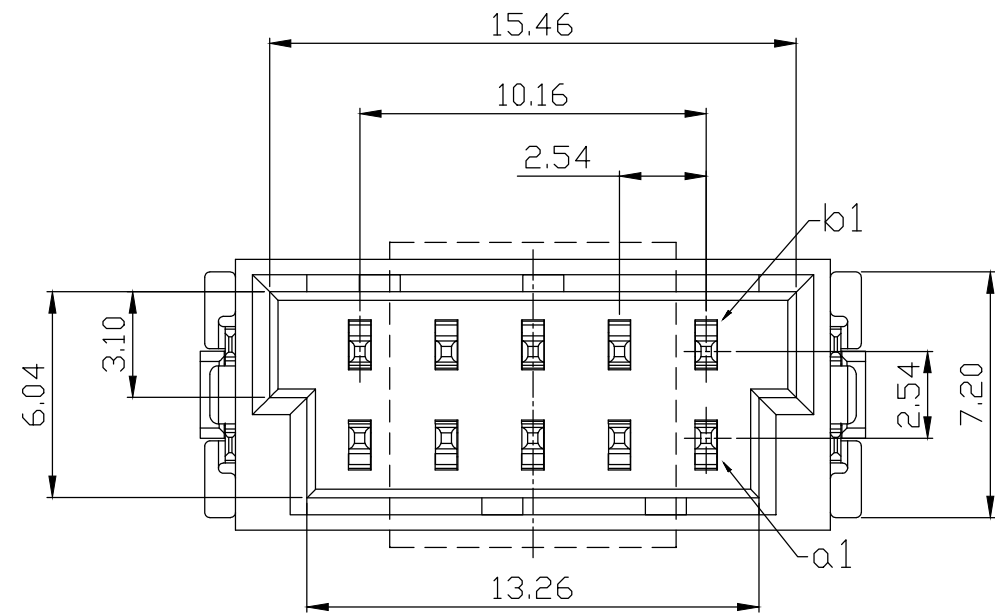
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6

7

H

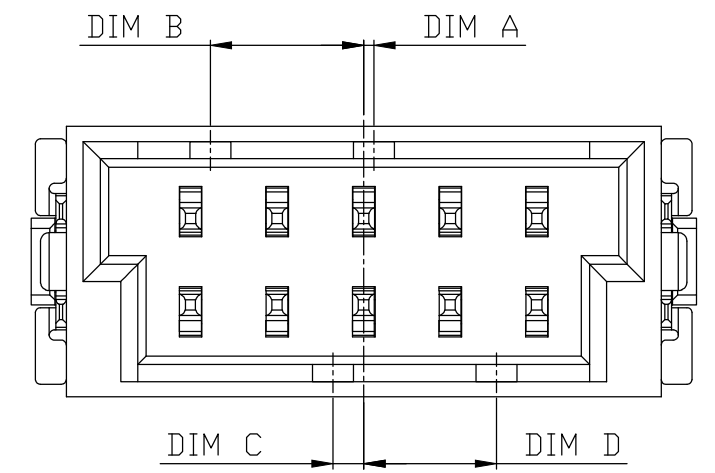
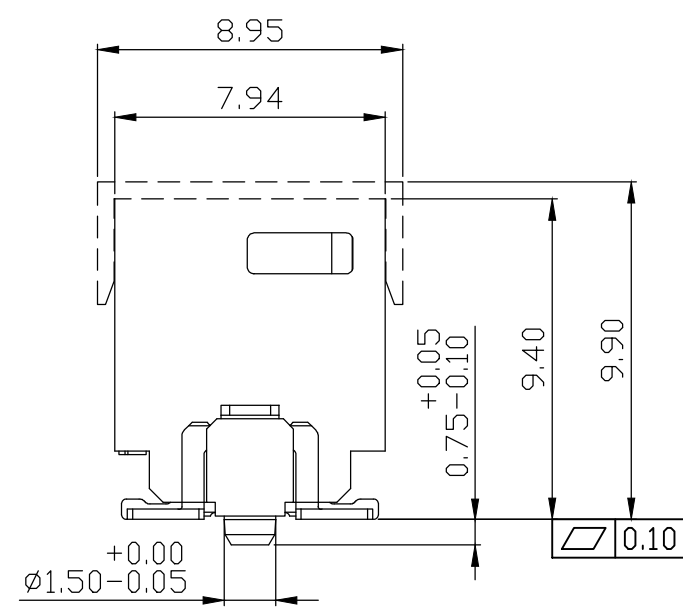
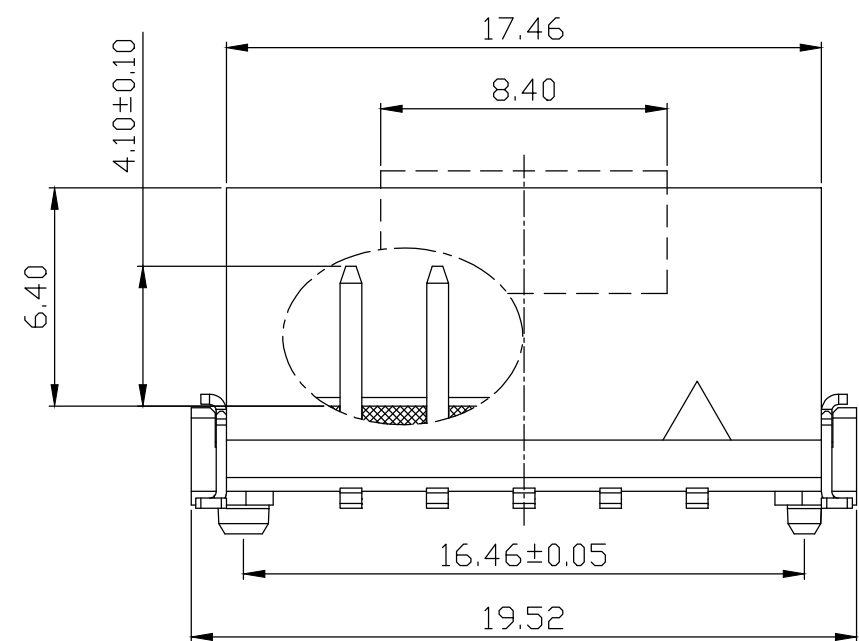
H



RECOMMENDED PCB LAYOUT(TOP VIEW)
PCB BOARD TOLERANCE:±0.05

NOTE:

- MATERIAL:**
 - 1.1 Insulator:LCP,UL94V-0,Black
 - 1.2 Contact:Copper Alloy
- FINISH**
 - 2.1 Contact: Au 15u" over nickel on contact area, Matte Tin over Nickel on solder area
- ELECTRICAL**
 - 3.1 Current Rating:12A Max.
 - 3.2 Contact Resistance:20mΩ Max.
 - 3.3 Withstand Voltage:2000V AC
 - 3.4 Insulation Resistance:1000 MΩ min
4. Operating temperature:-55°C TO +150°C
5. Soldering temperature:260°C for 3~5S
6. Packing: Tape Reel+Cap



COLOR	DIMENSION			
	DIM A	DIM B	DIM C	DIM D
BLACK	0.3	4.50	0.9	3.90

RoHS compliant
unit:mm

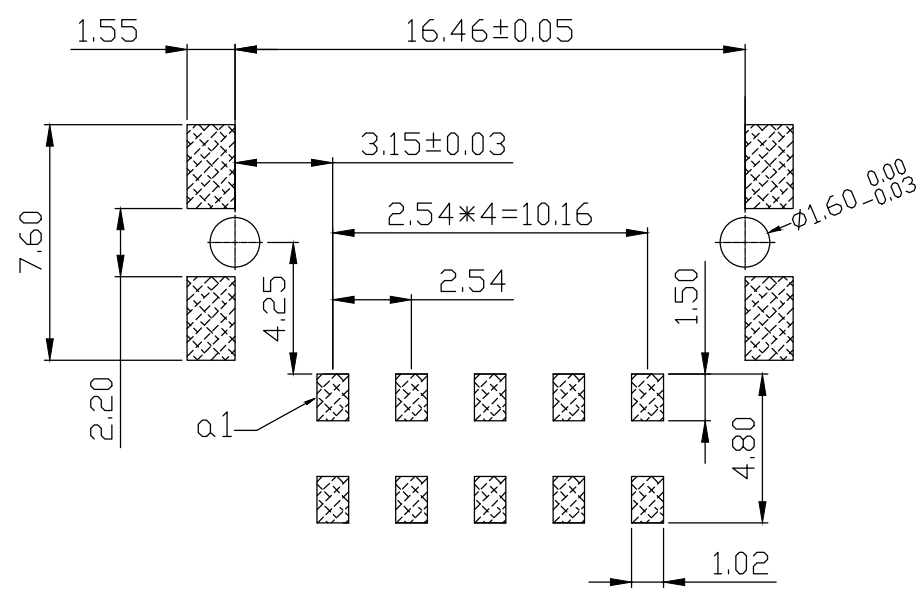
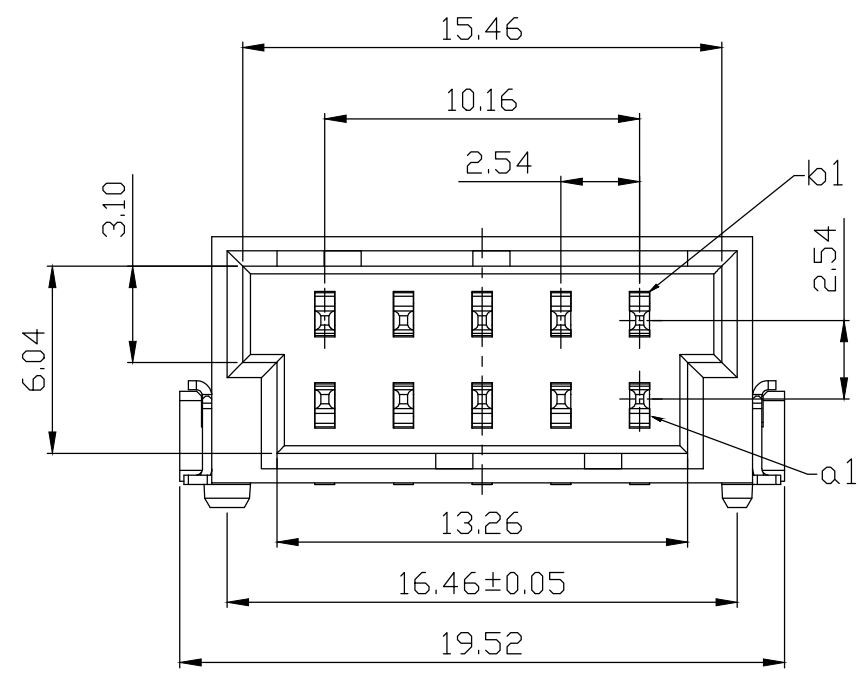
Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2025	Peter
Modification	Date	Name



Date	Name	Description: Wire to Board Wafer Pitch 2.54mm 10Pin SMT	
Drawn	03.03.2025	Peter	
Approved	03.03.2025	Peter	
Drawing-No.		ASS 10022 CO	
Customer-No.		rev00	
		Sheet 19 / 26	

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL



RECOMMENDED PCB LAYOUT(TOP VIEW)
PCB BOARD TOLERANCE:±0.05

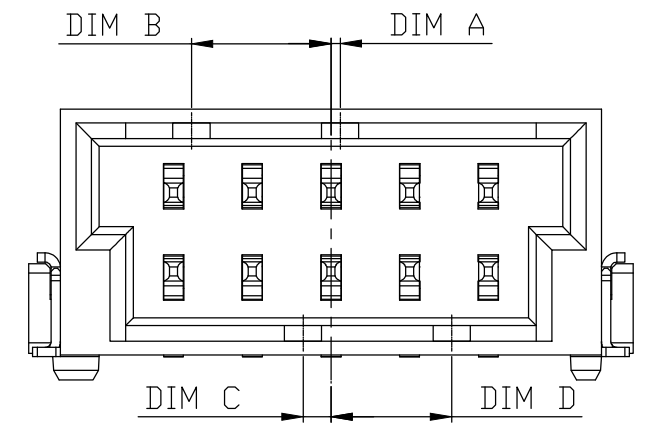
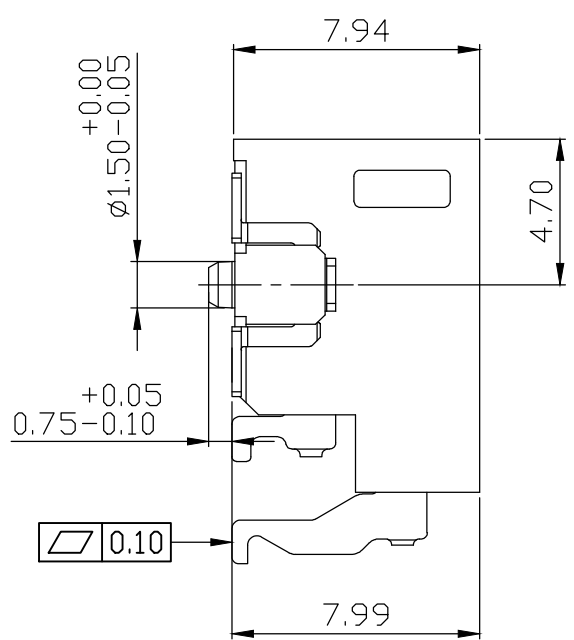
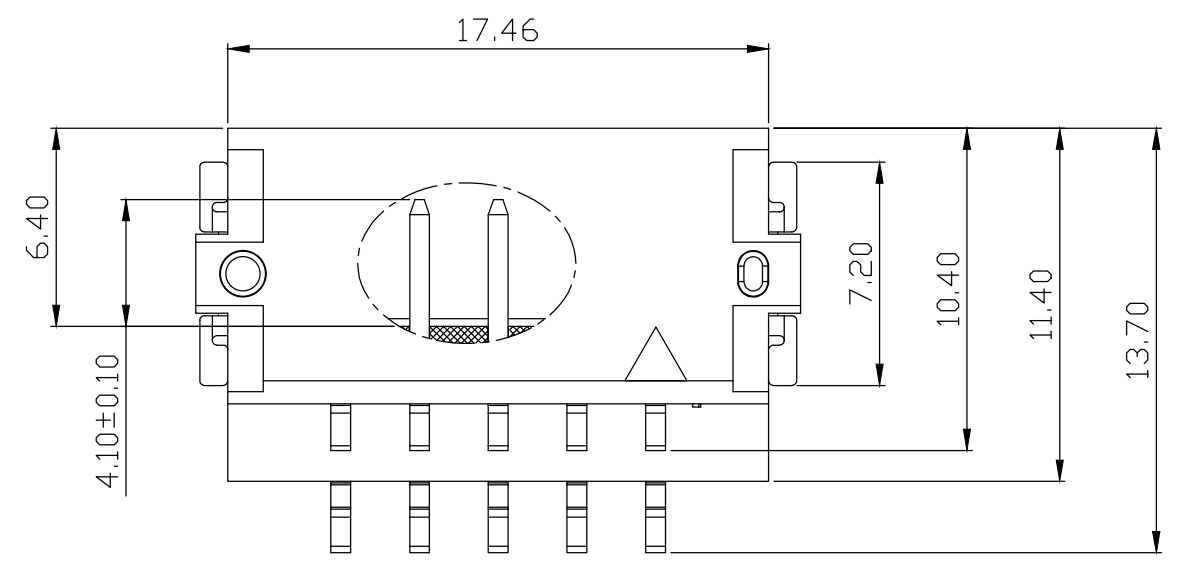
NOTE:

1. MATERIAL:
1.1 Insulator:LCP,UL94V-0,Black
1.2 Contact:Copper Alloy

2. FINISH
2.1 Contact: Au 15u" over nickel on contact area, Matte Tin over Nickel on solder area

3. ELECTRICAL
3.1 Current Rating: 12A Max.
3.2 Contact Resistance: 20mΩ Max.
3.3 Withstand Voltage: 2000V AC
3.4 Insulation Resistance: 1000 MΩ min

4. Operating temperature: -55°C TO +150°C
5. Soldering temperature: 260°C for 3~5S
6. Packing: Tape Reel



COLOR	DIMENSION			
	DIM A	DIM B	DIM C	DIM D
BLACK	0.3	4.50	0.9	3.90

RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2025	Peter	Date	Name
Approved	03.03.2025	Peter		
Modification	Date	Name		



Description: Wire to Board Wafer Pitch 2.54mm 10Pin R/A SMT	
ASSMANN WSW-NO. A-WBP-M005DA-10SR1	
Drawing-No. ASS 10022 CO	rev00
Customer-No.	Sheet 20 / 26

1

2

3

4

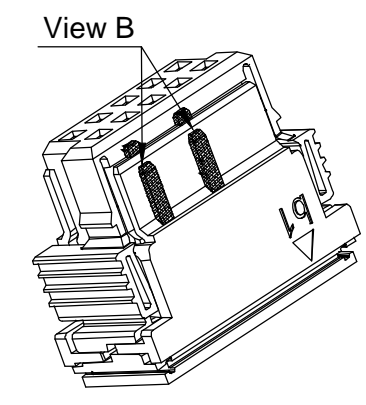
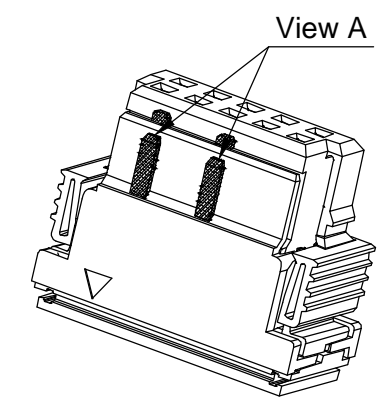
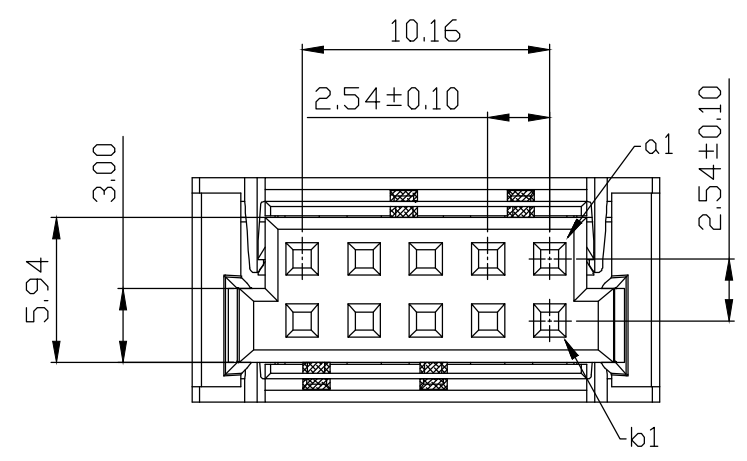
5

6

7

A

A



NOTE:

- 1.MATERIAL:
 - 1.1 Housing:PA46,UL94V-0,Black
- 2.ELECTRICAL
 - 2.1 Withstand Voltage:2000V AC
 - 2.2 Insulation Resistance:1000 MΩ min
- 3.Operating temperature:-55°C TO +125°C
- 4.Packing:Tray

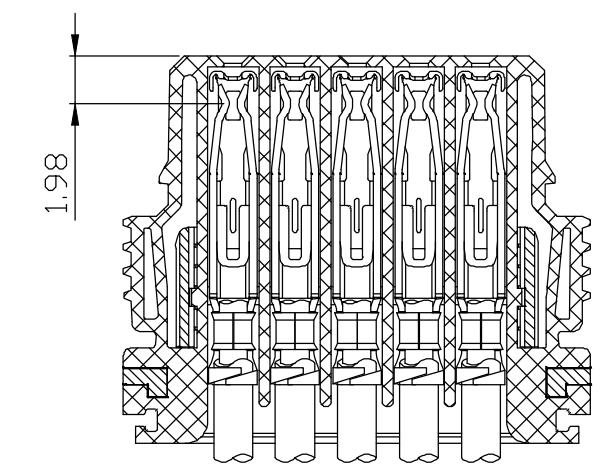
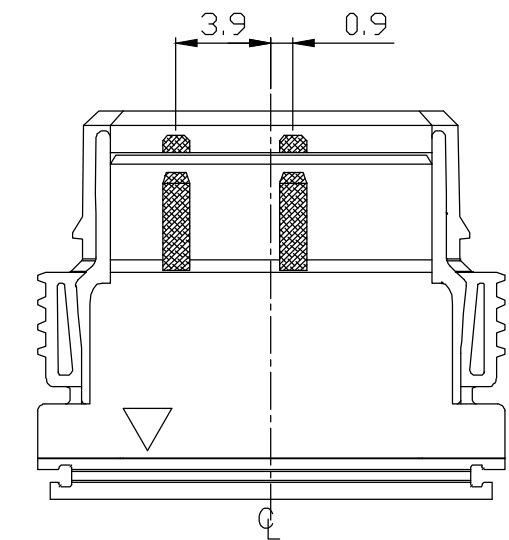
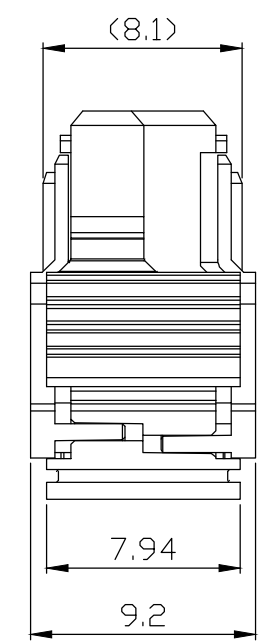
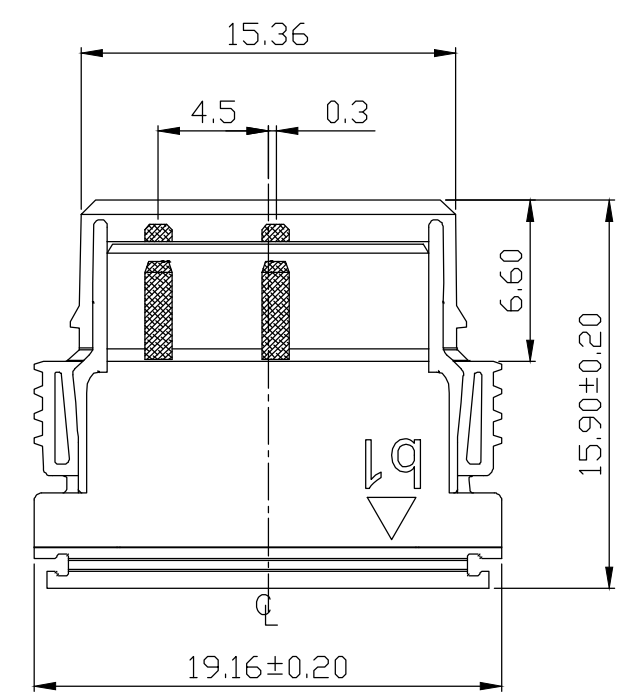
B

B

Fool Proof Diagram

C

C



Terminal Diagram

D

D

E

E

F

F

G

G

RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2025	Peter
Approved	03.03.2025	Peter
Modification	Date	Name

Date

Name

Drawn 03.03.2025 Peter

Approved 03.03.2025 Peter

ASSMANN
WSW components
A company of BCS

Description: Wire to Board Housing Pitch 2.54mm 10Pin	
ASSMANN WSW-NO. A-WBH-M005DG-10CP1	
Drawing-No. ASS 10022 CO	rev00
Customer-No.	Sheet 21 / 26

H

H

1

2

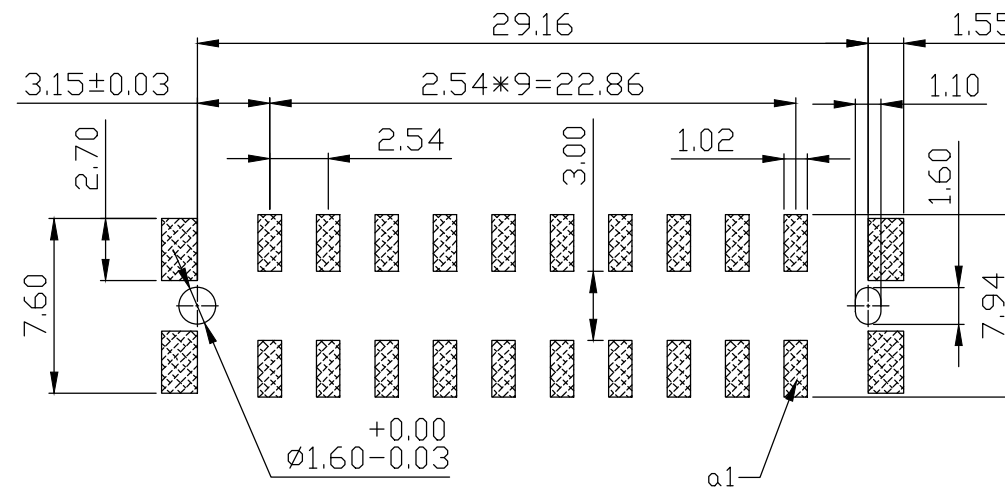
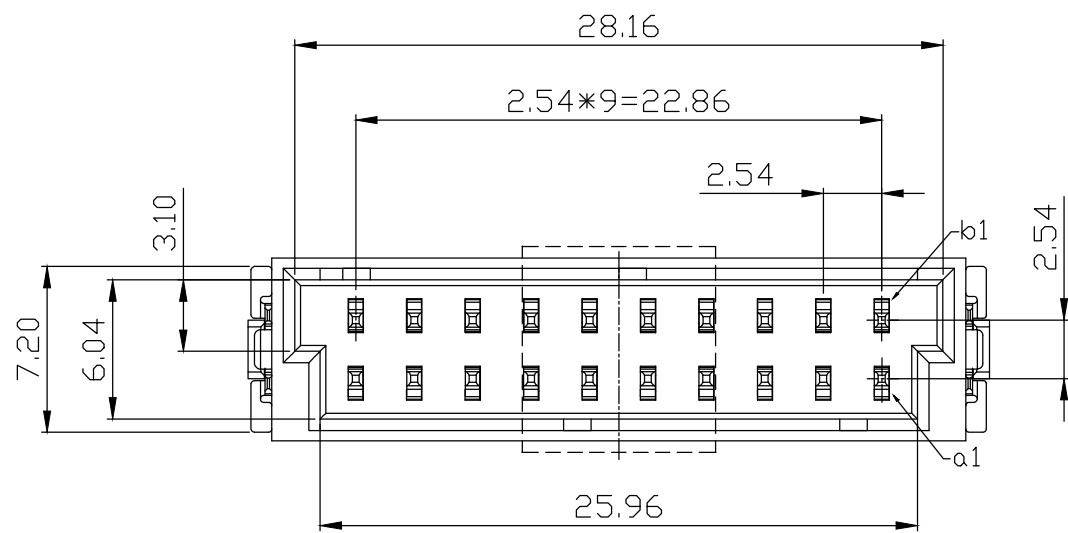
3

4

5

6

7



RECOMMENDED PCB LAYOUT (TOP VIEW)
PCB BOARD TOLERANCE: ±0.05

NOTE:

1. MATERIAL:

- 1.1 Insulator: LCP, UL94V-0, Black
- 1.2 Contact: Copper Alloy

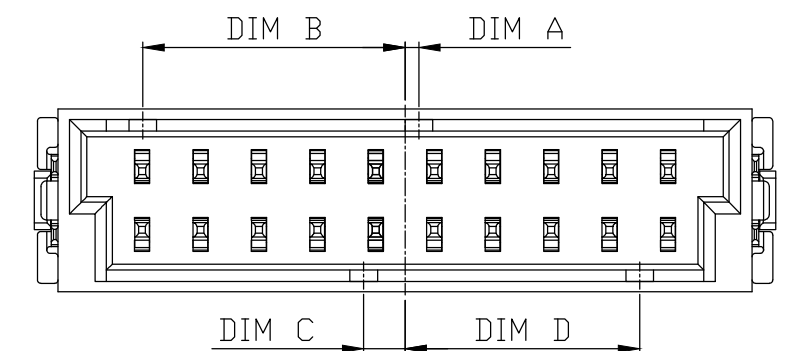
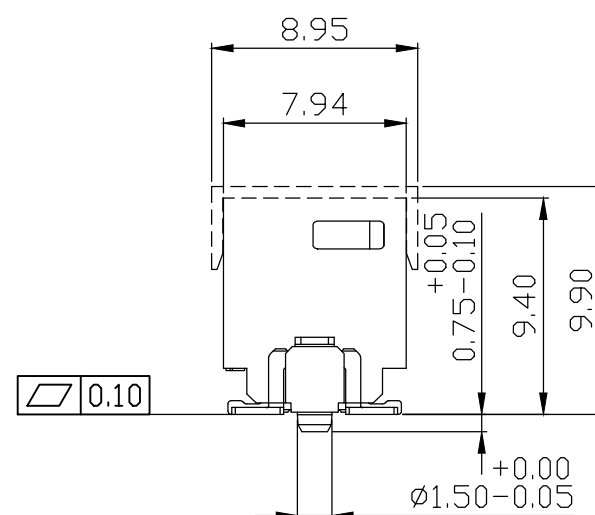
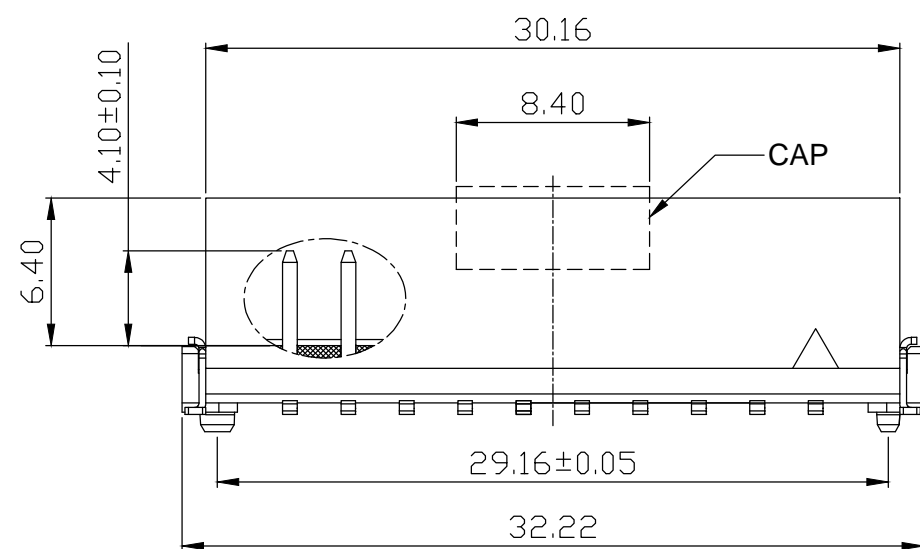
2. FINISH

- 2.1 Contact: Au 15u" over nickel on contact area, Matte Tin over Nickel on solder area

3. ELECTRICAL

- 3.1 Current Rating: 12A Max.
- 3.2 Contact Resistance: 20mΩ Max.
- 3.3 Withstand Voltage: 2000V AC
- 3.4 Insulation Resistance: 1000 MΩ min

- 4. Operating temperature: -55°C TO +150°C
- 5. Soldering temperature: 260°C for 3~5S
- 6. Packing: Tape Reel+Cap



COLOR	DIMENSION			
	DIM A	DIM B	DIM C	DIM D
BLACK	0.6	11.4	1.8	10.2

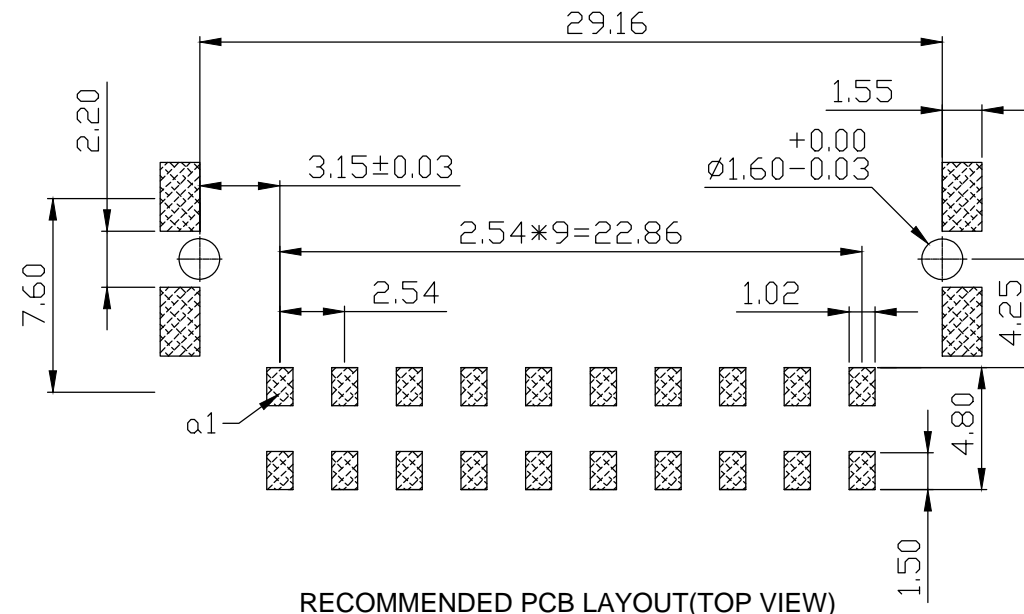
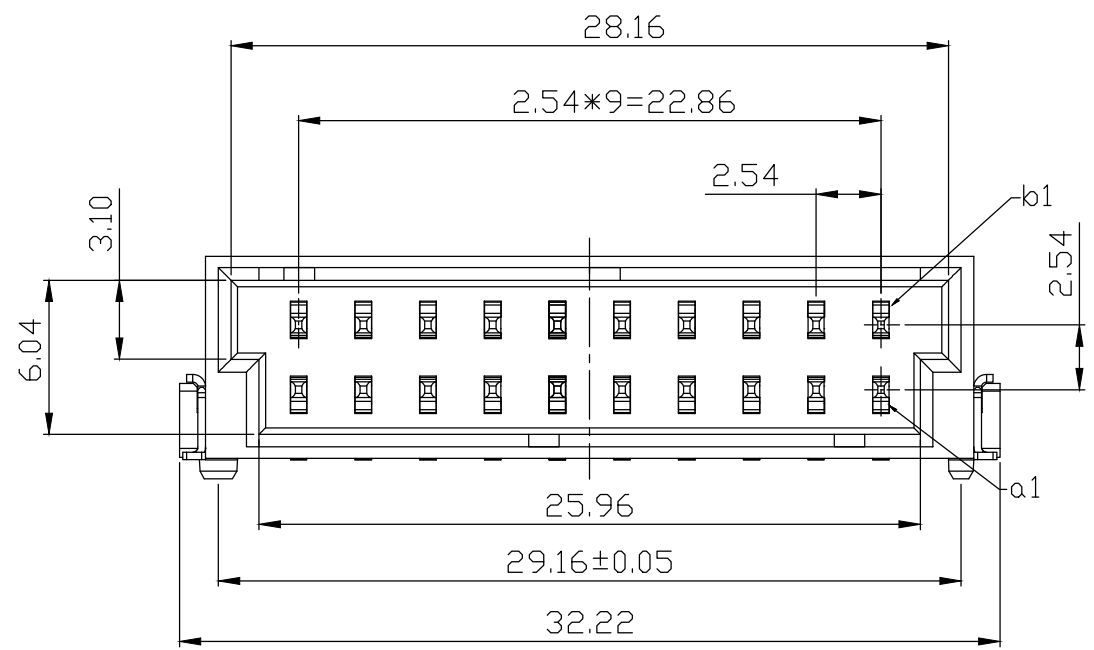
RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2025	Peter
Modification	Date	Name

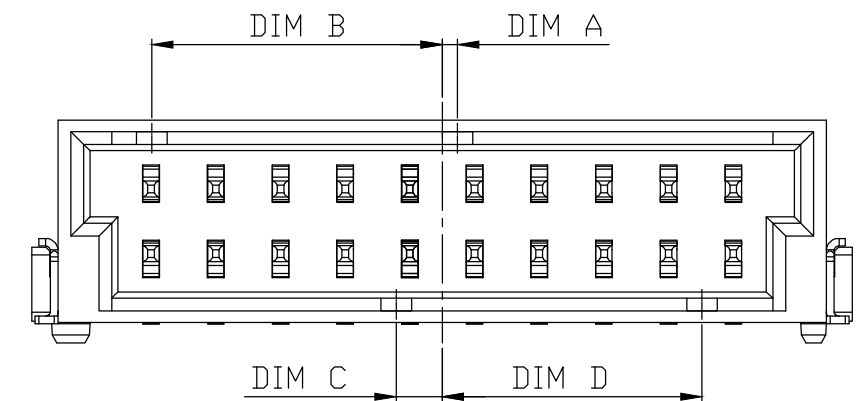
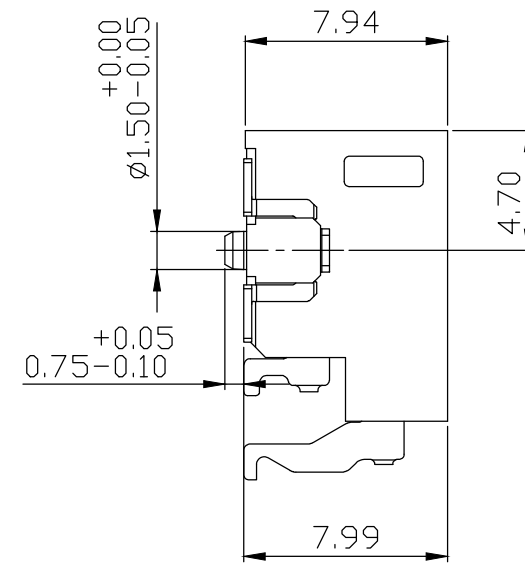
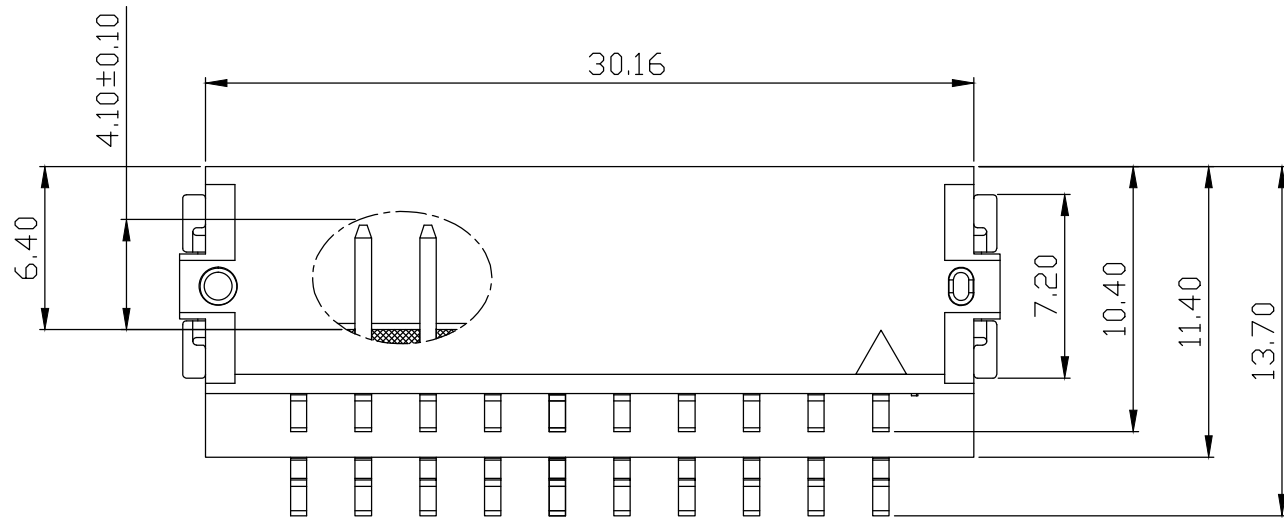


Date	03.03.2025	Name	Peter	Description: Wire to Board Wafer Pitch 2.54mm 20Pin Straight SMT
Drawn	03.03.2025	Name	Peter	
ASSMANN WSW-NO.				A-WBP-M005DG-20SR1
Drawing-No.				
ASS 10022 CO			rev00	
Customer-No.			Sheet	
			22 / 26	



RECOMMENDED PCB LAYOUT(TOP VIEW)
PCB BOARD TOLERANCE:±0.05

- NOTE:**
- MATERIAL:**
 - Insulator:LCP,UL94V-0,Black
 - Contact:Copper Alloy
 - FINISH**
 - Contact: Au 15u" over nickel on contact area, Matte Tin over Nickel on solder area
 - ELECTRICAL**
 - Current Rating:12A Max.
 - Contact Resistance:20mΩ Max.
 - Withstand Voltage:2000V AC
 - Insulation Resistance:1000 MΩ min
 - Operating temperature:-55°C TO +150°C
 - Soldering temperature:260°C for 3~5S
 - Packing: Tape Reel



COLOR	DIMENSION			
	DIM A	DIM B	DIM C	DIM D
BLACK	0.6	11.4	1.8	10.2

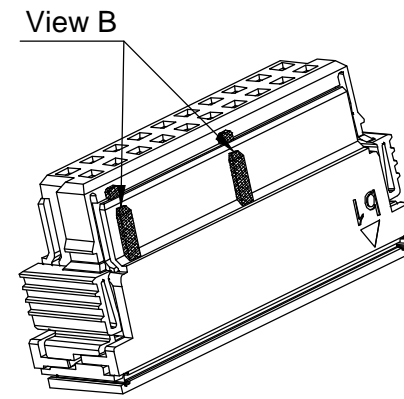
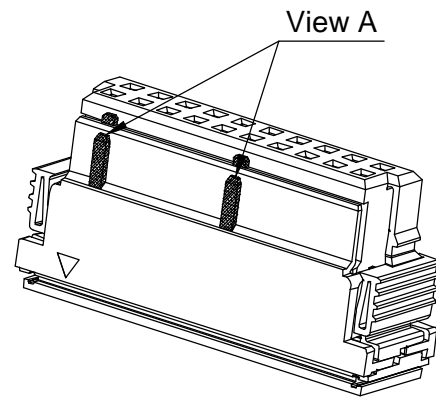
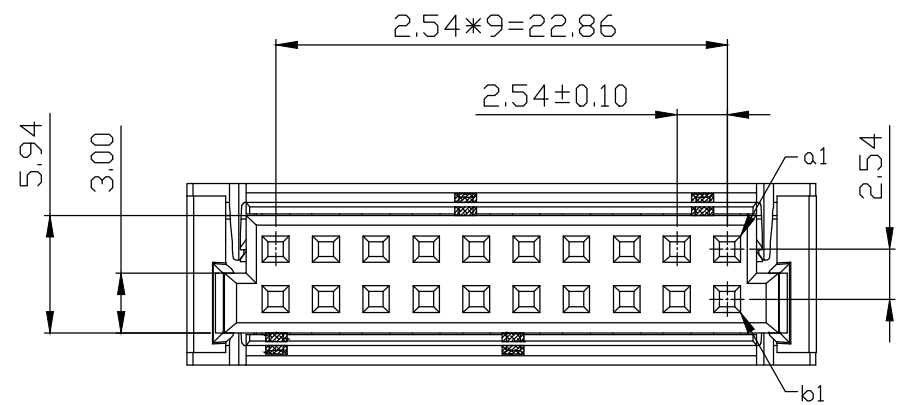
RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2025	Peter
Modification	Date	Name



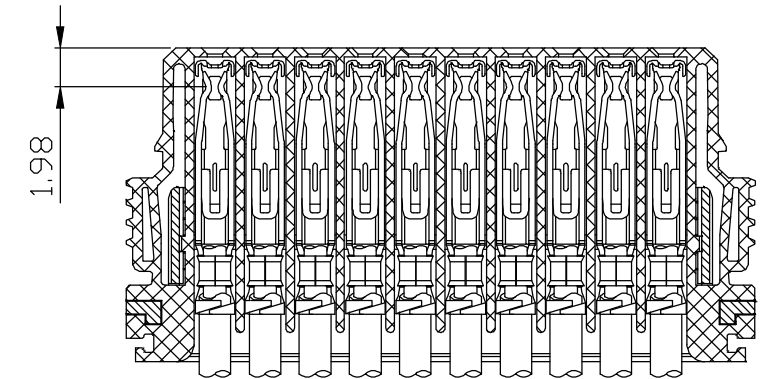
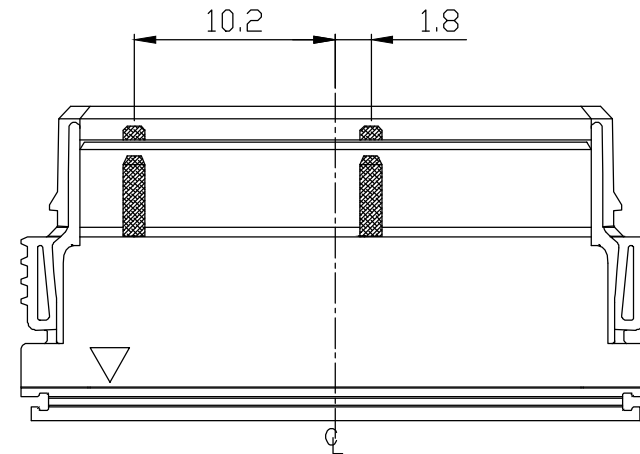
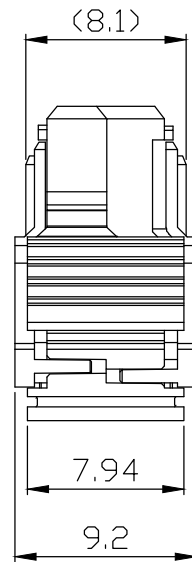
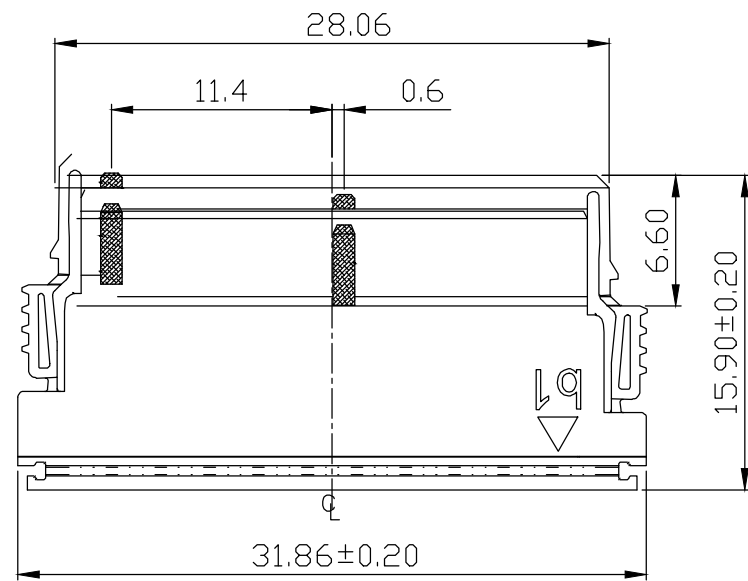
Date	Name	Description: Wire to Board Wafer Pitch 2.54mm 20Pin R/A SMT	
Drawn	03.03.2025	Peter	
Approved	03.03.2025	Peter	
ASSMANN WSW-NO.		A-WBP-M005DA-20SR1	
Drawing-No.		ASS 10022 CO	rev00
Customer-No.		Sheet 23 / 26	



NOTE:

- 1.MATERIAL:
 - 1.1 Housing:PA46,UL94V-0,Black
- 2.ELECTRICAL
 - 2.1 Withstand Voltage:2000V AC
 - 2.2 Insulation Resistance:1000 MΩ min
- 3.Operating temperature:-55°C TO +125°C
- 4.Packing:Tray

Fool Proof Diagram




Terminal Diagram

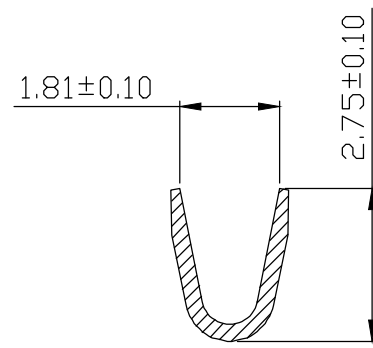
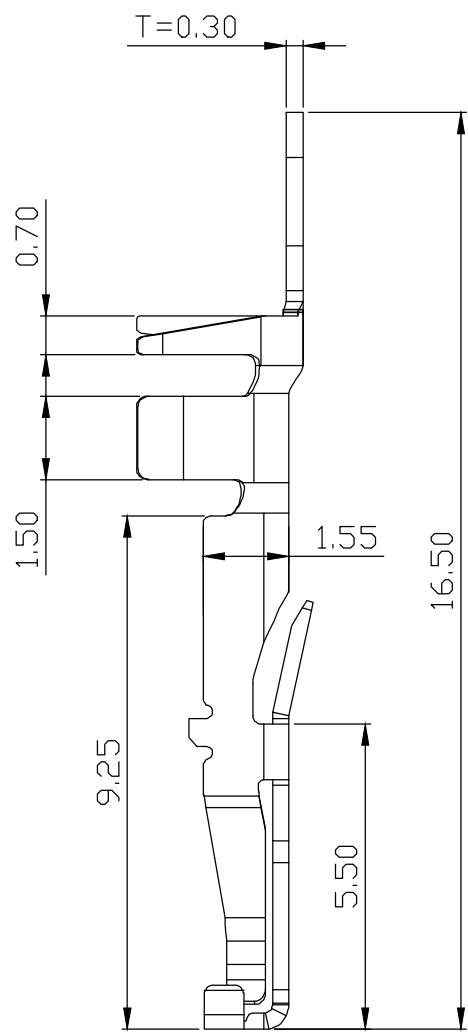
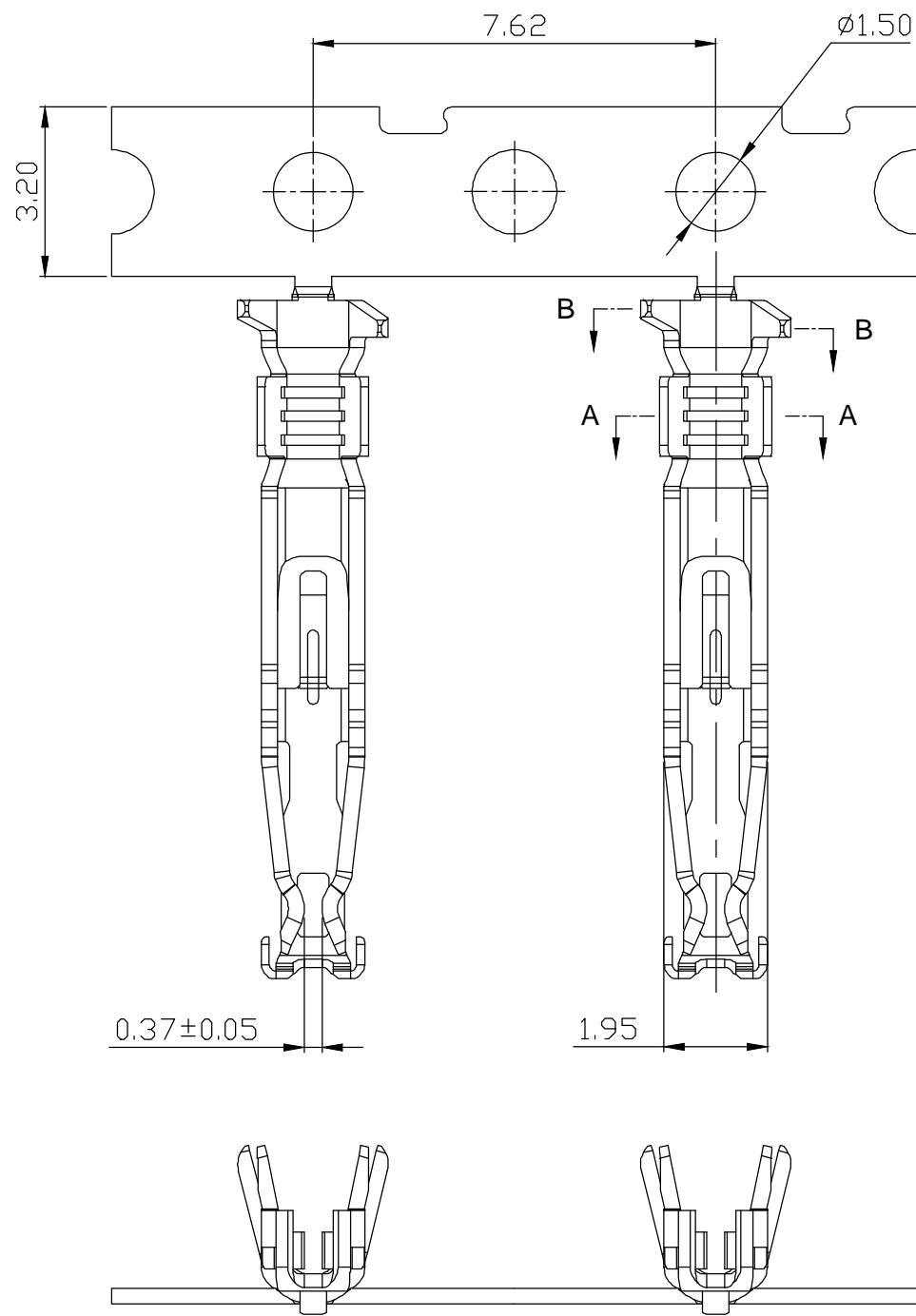
RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

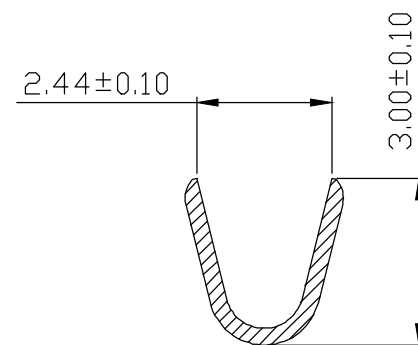
Drawn	03.03.2025	Peter
Approved	03.03.2025	Peter
Date	Name	
Modification	Date	Name


 A company of 

Description: Wire to Board Housing Pitch 2.54mm 20Pin	
ASSMANN WSW-NO. A-WBH-M005DG-20CP1	
Drawing-No. ASS 10022 CO	rev00
Customer-No.	Sheet 24 / 26



SECTION:A-A

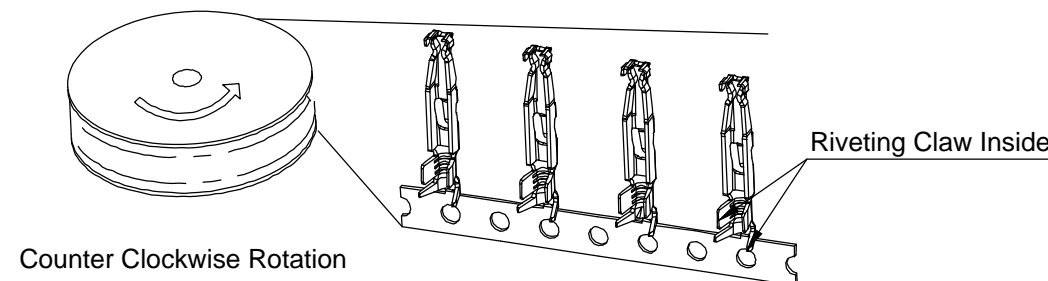
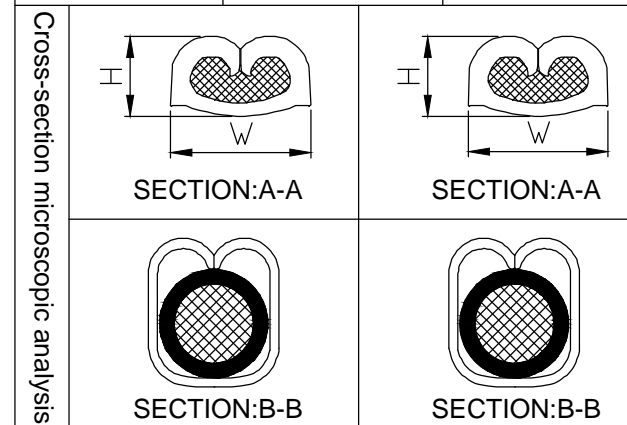


SECTION:B-B

NOTE:

- 1.MATERIAL:
1.1 Contact:Cu-Alloy
 - 2.ELECTRICAL
2.1 Current Rating:12A Max.
 - 3.Wire Range:20-18AWG
 - 4.Insulation OD.:1.45~1.90mm
 - 5.Operating temperature:-55°C TO +125°C
 - 6.Packing:Reel
- Order Code:
A-WBT-M005EG-01CR1: Au 15u"/Matte tin
A-WBT-M005EG-01CR2: Tin over Nickle

	18AWG	20AWG
DIM H	1.35±0.05	1.13±0.05
DIM W	1.90±0.05	1.90±0.05
Compression	87.6%	87.9%



RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2025	Peter
Modification	Date	Name

Date Name

Drawn	03.03.2025	Peter
Approved	03.03.2025	Peter

ASSMANN
WSW components
A company of BCS

Description: Wire to Board Female Terminal	
ASSMANN WSW-NO. A-WBT-M005EG-01CRx	
Drawing-No. ASS 10022 CO	rev00
Customer-No.	Sheet 25 / 26

1

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6

7

A

A

B

B

C

C

D

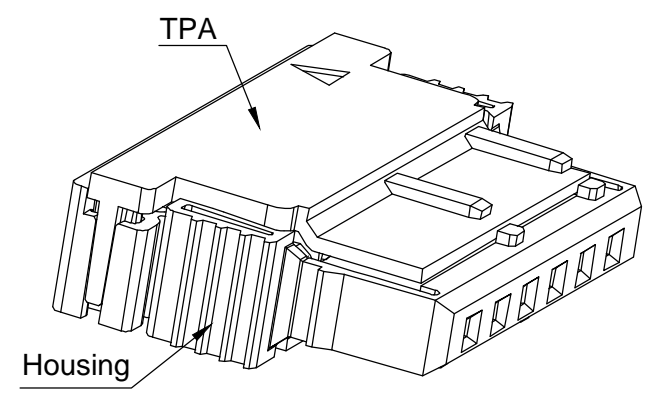
D

E

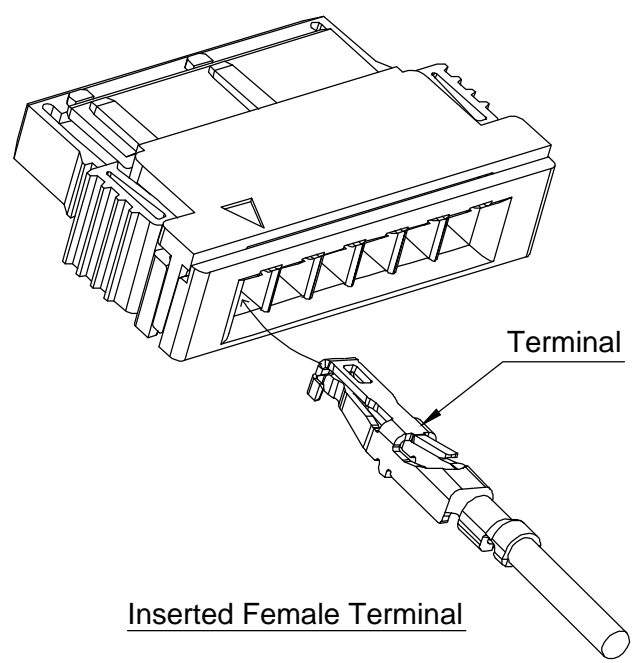
E

F

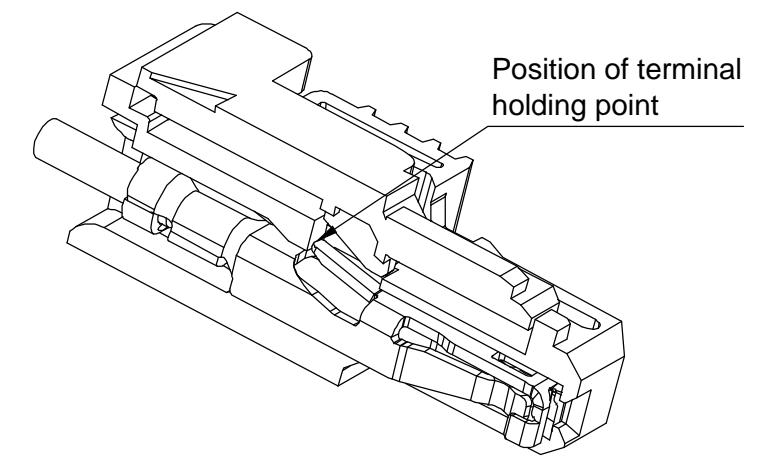
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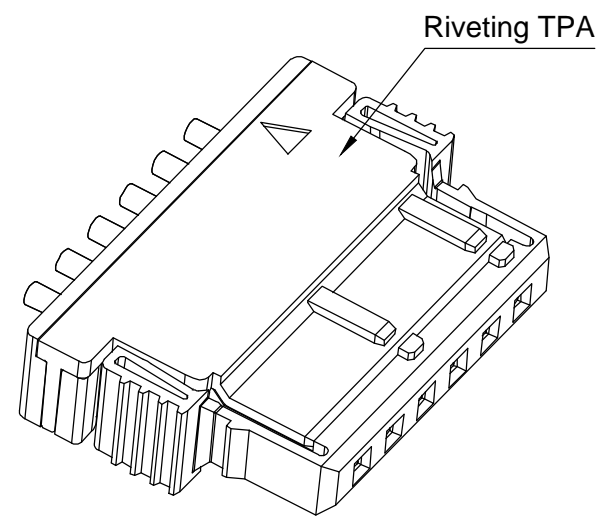
Cover Loose Mounted



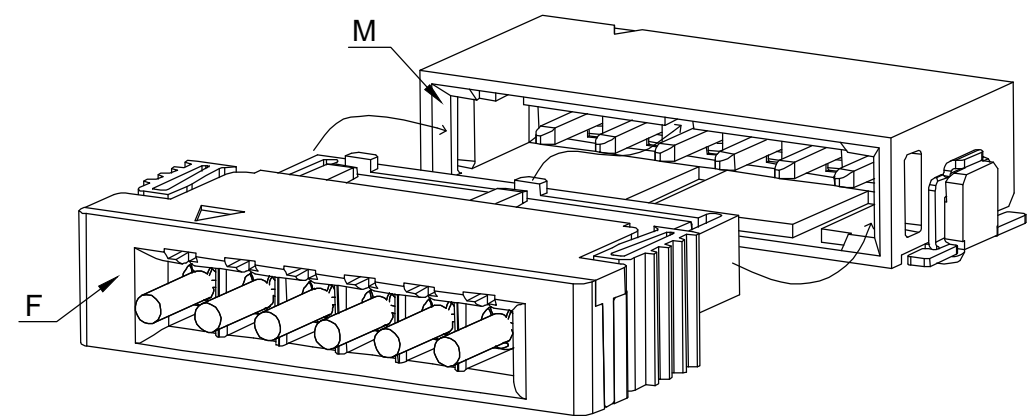
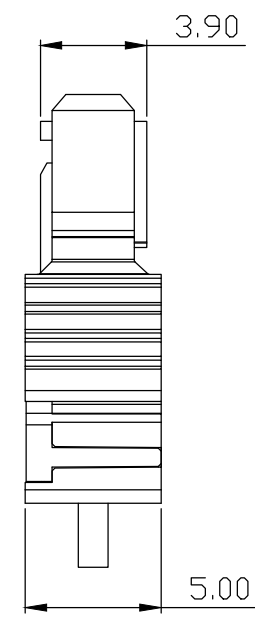
Inserted Female Terminal



Internal Structure Diagram



Riveting Diagram



Male/Female Mating

G

G

RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
.X	±0.40
.XX	±0.25
.XXX	±0.15
DIM	TOL
X.°	±3°
Angle	TOL

Drawn	03.03.2025	Peter
Modification	Date	Name

Date: 03.03.2025
Name: Peter

Drawn: 03.03.2025
Approved: 03.03.2025
Peter

ASSMANN
WSW components
A company of BCS

Description: Wire to Board Mating Diagram	
ASSMANN WSW-NO.	
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